

TUCANA Block Diagram

PROJECT CODE : 91.4KK01.001
PCB P/N : 48.4KK01.0SB
REVISION : S0201-SB

Clock Generator
ICS9LVS3197BKLFT
3

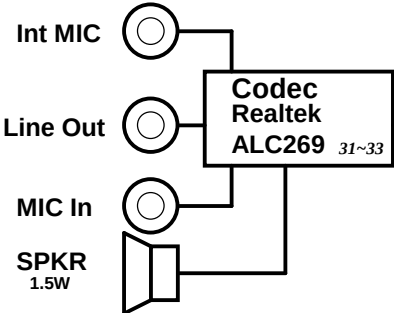
Thermal Sensor
GMT G787
37

Slot 0
DDRIII 800 21
DDRIII Channel A

Slot 1
DDRIII 800 22
DDRIII Channel B

Intel CPU
SFF
4,5,...,10,11

FDI x8 DMI x4



HDD 26
0

Flash ROM 4MB 39
SATA

INTEL
PCH
14 USB 2.0/1.1 ports
ETHERNET (10/100/1000Mb)
High Definition Audio
6 SATA ports
8 PCIE ports
ACPI 1.1
LPC I/F
PCI/PCI BRIDGE
12,13,...,19,20

LVDS LCD 23

RGB CRT 24

PCle HDMI 25

9 CAMERA 23

0,1,4 USB Port x 3 28

12 Blue Tooth 27

2 Cardreader 34

MS Pro Duo
/SD(SDHC) 34

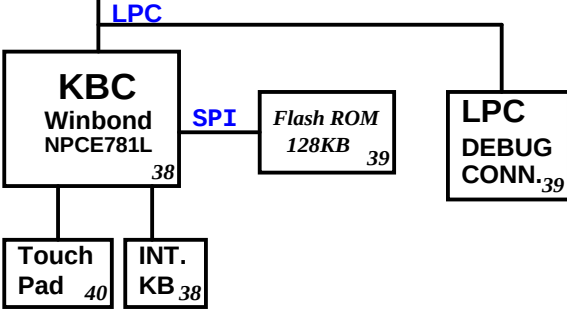
8 Mini 1 Card
WLAN/ WIMAX 35

1

Giga LAN Atheros AR8131M 29

TXFM 30

RJ45 30



PCB STACKUP

TOP L1

VCC L2

S L3

S L4

GND L5

BOTTOM L6

SMbus ADDRESS

DIMM 1	1010 000x b
DIMM 2	1010 001x b
CLK GEN	1110 001x b
Thermal Sensor	0101 110x b
CHARGER	0001 001x b
BATTERY	0001 110x b

DVT 1ST

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Wistron Corporation

21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.

Title

BLOCK DIAGRAM

Size A3

Document Number

TUCANA

Rev SB

Date: Wednesday, July 07, 2010

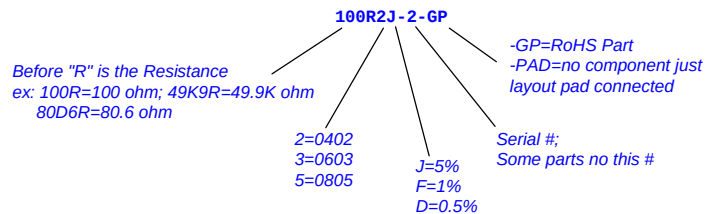
Sheet 1 of 56

SYSTEM DC/DC RT8223 47	
INPUTS	OUTPUTS
DCBATOUT	5V_S5(6A) 3D3V_S5(5A) 5V_AUX_S5 3D3V_AUX_S5
RT8209 49	
INPUTS	OUTPUTS
DCBATOUT	1D05V_S0(20A)
RT8209 48	
INPUTS	OUTPUTS
DCBATOUT	1D5V_S3(9.4A)
RT9026 51	
INPUTS	OUTPUTS
5V_S5	DDR_VREF_S3 1.2A
CHARGER BQ24751 52	
INPUTS	OUTPUTS
DCBATOUT	CHG_PWR 18V 6.0A
CPU DC/DC ADP3211 46	
INPUTS	OUTPUTS
DCBATOUT	VCC_CORE 27A
GFX Core ADP3211 50	
INPUTS	OUTPUTS
DCBATOUT	VCC_GFXCORE 11A

PCH Strapping

Name	Schematics Notes
SPKR	Reboot option at power-up Default Mode: Internal weak Pull-down. No Reboot Mode with TCO Disabled: Connect to Vcc3_3 with 8.2-kΩ - 10-kΩ weak pull-up resistor.
INIT3_3V#	Weak internal pull-down. Do not pull high.
GNT3#/ GPIO55	Default Mode: Internal pull-up. Low (0) = Top Block Swap Mode (Connect to ground with 4.7-kΩ weak pull-down resistor).
INTVRMEN	High (1) = Integrated VRM is enabled Low (0) = Integrated VRM is disabled
GNT0#, GNT1#	Default (SPI): Left both GNT0# and GNT1# floating. No pull up required. Boot from PCI: Connect GNT1# to ground with 1-kΩ pull-down resistor. Leave GNT0# Floating. Boot from LPC: Connect both GNT0# and GNT1# to ground with 1-kΩ pull-down resistor.
GNT2#/ GPIO53	Default - Internal pull-up. Low (0)= Configures DMI for ESI compatible operation (for servers only. Not for mobile/desktops).
GPIO33	Default: Do not pull low. Disable ME in Manufacturing Mode: Connect to ground with 1-kΩ pull-down resistor.
SPI_MOSI	Enable iTPM: Connect to Vcc3_3 with 8.2-kΩ weak pull-up resistor. Disable iTPM: Left floating, no pull-down required.
NV_ALE	Enable Danbury: Connect to Vcc3_3 with 8.2-kΩ weak pull-up resistor. Disable Danbury: Connect to ground with 4.7-kΩ weak pull-down resistor.
NC_CLE	Weak internal pull-up. Do not pull low.
HAD_DOCK_EN#/ GPIO[33]	Low (0): Flash Descriptor Security will be overridden. High (1) : Flash Descriptor Security will be in effect.
HDA_SDO	Weak internal pull-down. Do not pull high.
HDA_SYNC	Weak internal pull-down. Do not pull high.
GPIO15	Weak internal pull-down. Do not pull high.
GPIO8	Weak internal pull-up. Do not pull low.
GPIO27	Default = Do not connect (floating) High(1) = Enables the internal VccVRM to have a clean supply for analog rails. No need to use on-board filter circuit. Low (0) = Disables the VccVRM. Need to use on-board filter circuits for analog rails.

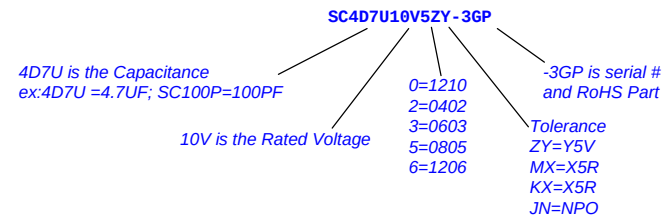
Resistor



Processor Strapping

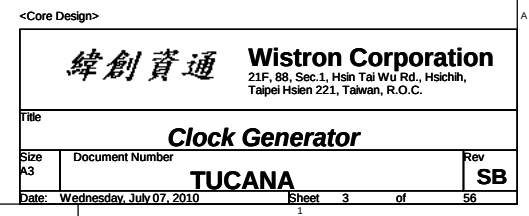
Pin Name	Strap Description	Configuration (Default value for each bit is 1 unless specified otherwise)	Default Value
CFG[4]	Embedded DisplayPort Presence	1: Disabled - No Physical Display Port attached to Embedded DisplayPort. 0: Enabled - An external Display Port device is connected to the Embedded Display Port.	1
CFG[3]	PCI-Express Static Lane Reversal	1: Normal Operation. 0: Lane Numbers Reversed 15 -> 0, 14 -> 1, ...	1
CFG[0]	PCI-Express Configuration Select	1: Single PCI-Express Graphics 0: Bifurcation enabled	1
CFG[7]	Reserved - Temporarily used for early Clarksfield samples.	Clarksfield (only for early samples pre-ES1) - Connect to GND with 3.01K Ohm/5% resistor Note: Only temporary for early CFD samples (rPGA/BGA) [For details please refer to the WW33 MoW and sighting report]. For a common motherboard design (for AUB and CFD), the pull-down resistor should be used. Does not impact AUB functionality.	0

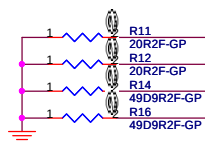
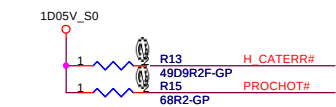
Capacitor



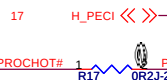
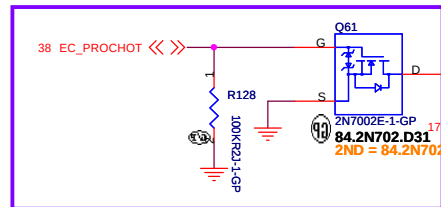
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Reference			
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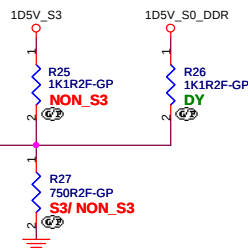


From PCH

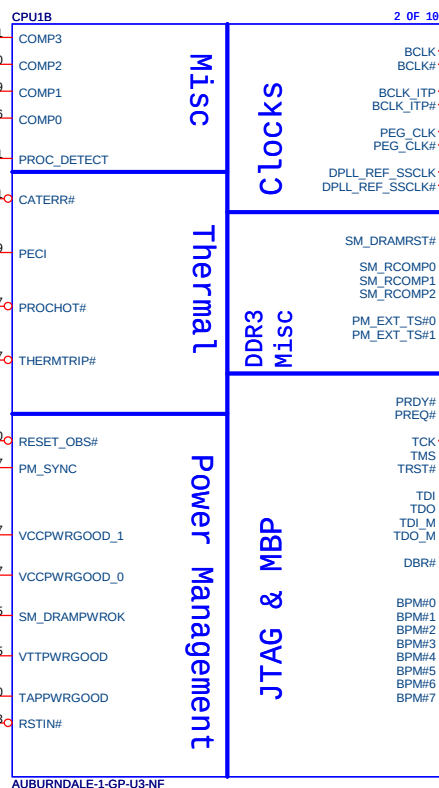
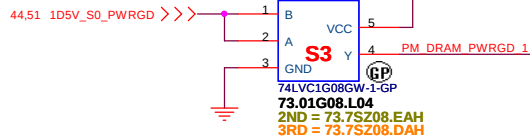
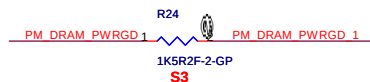
14 PM_DRAM_PWRGD >>>

49 H_VTTPWRGD >>>

16,29,34,35,38,39,44 PLT_RST# >>>



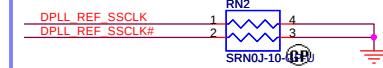
NON_S3: 3Kohm
S3: 750ohm



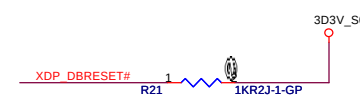
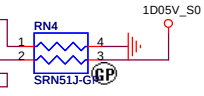
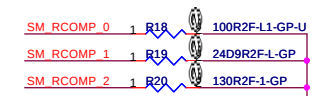
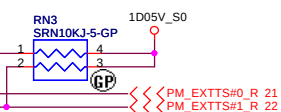
Clocks

DDR3 Misc

JTAG & MBP



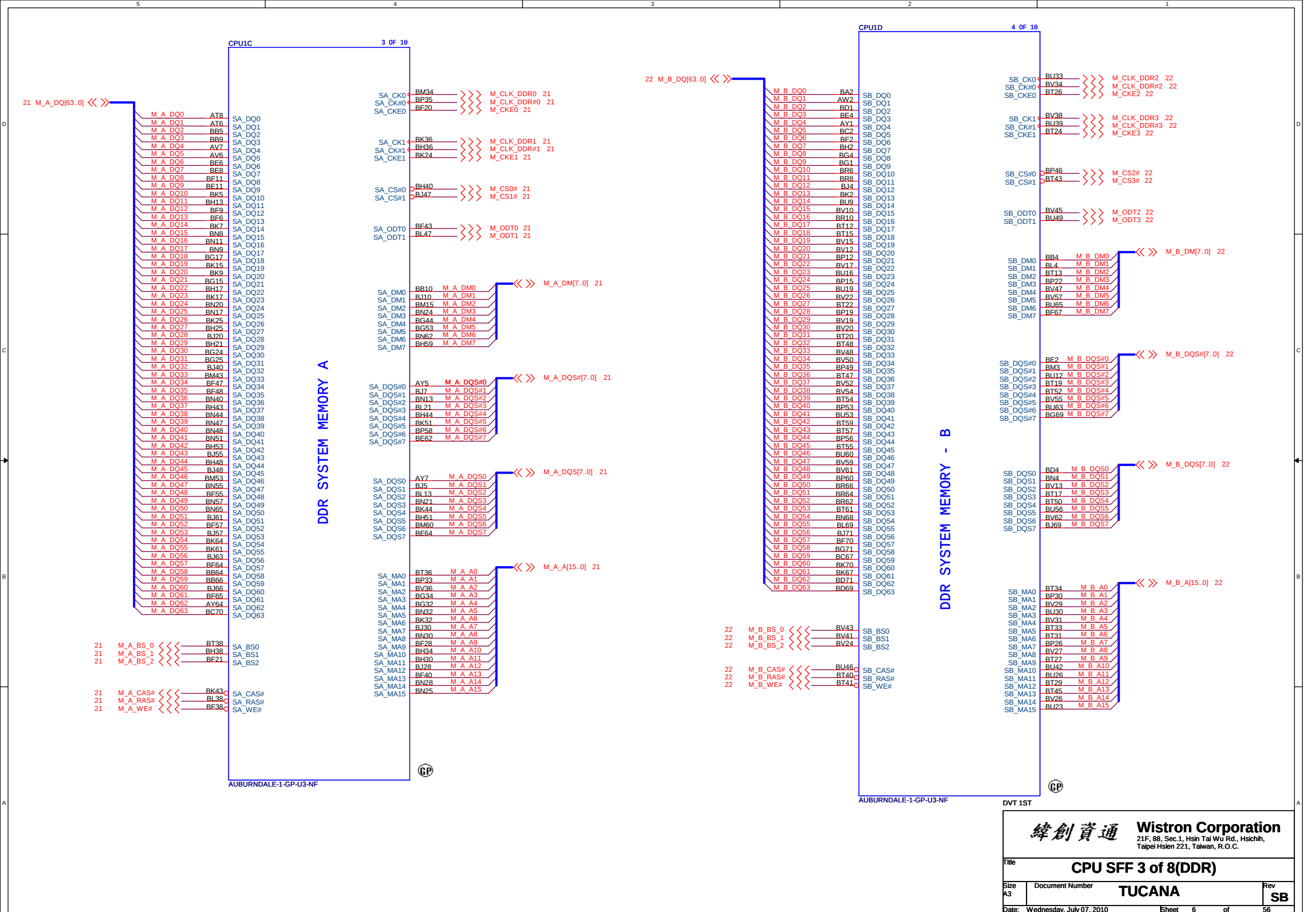
If supports integrated graphics but without Embedded DisplayPort(eDP), these pins can also be connected to GND directly.

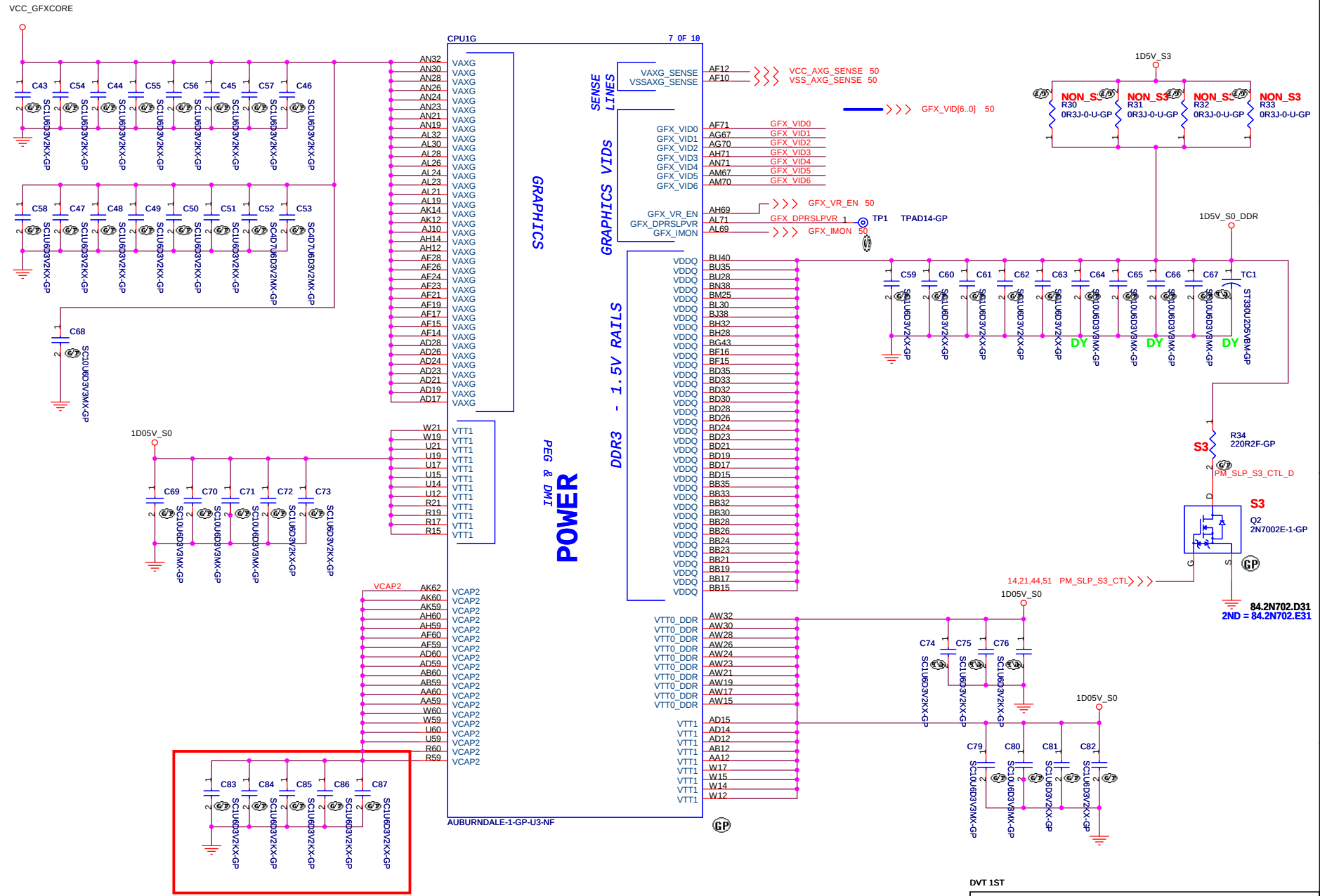


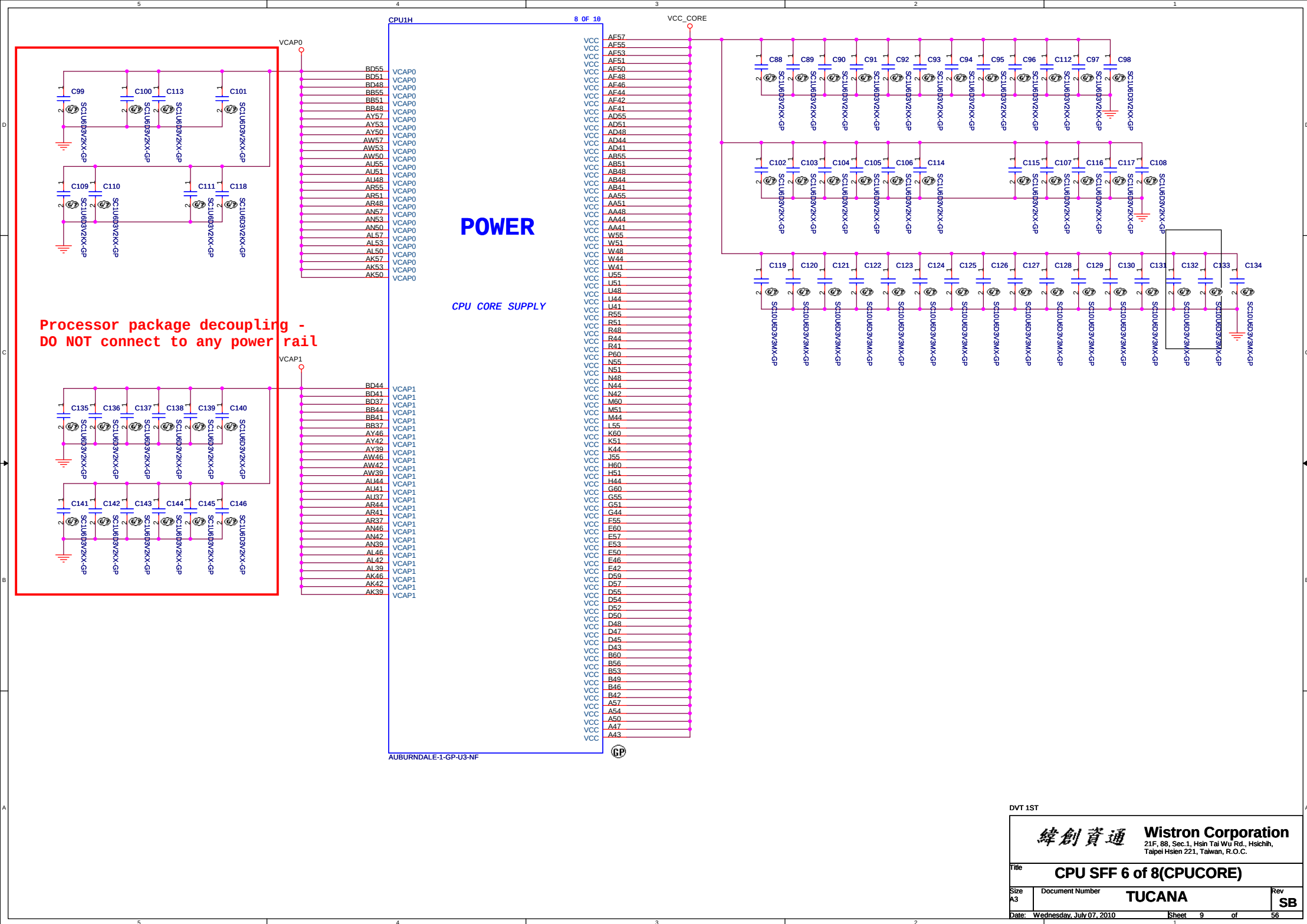
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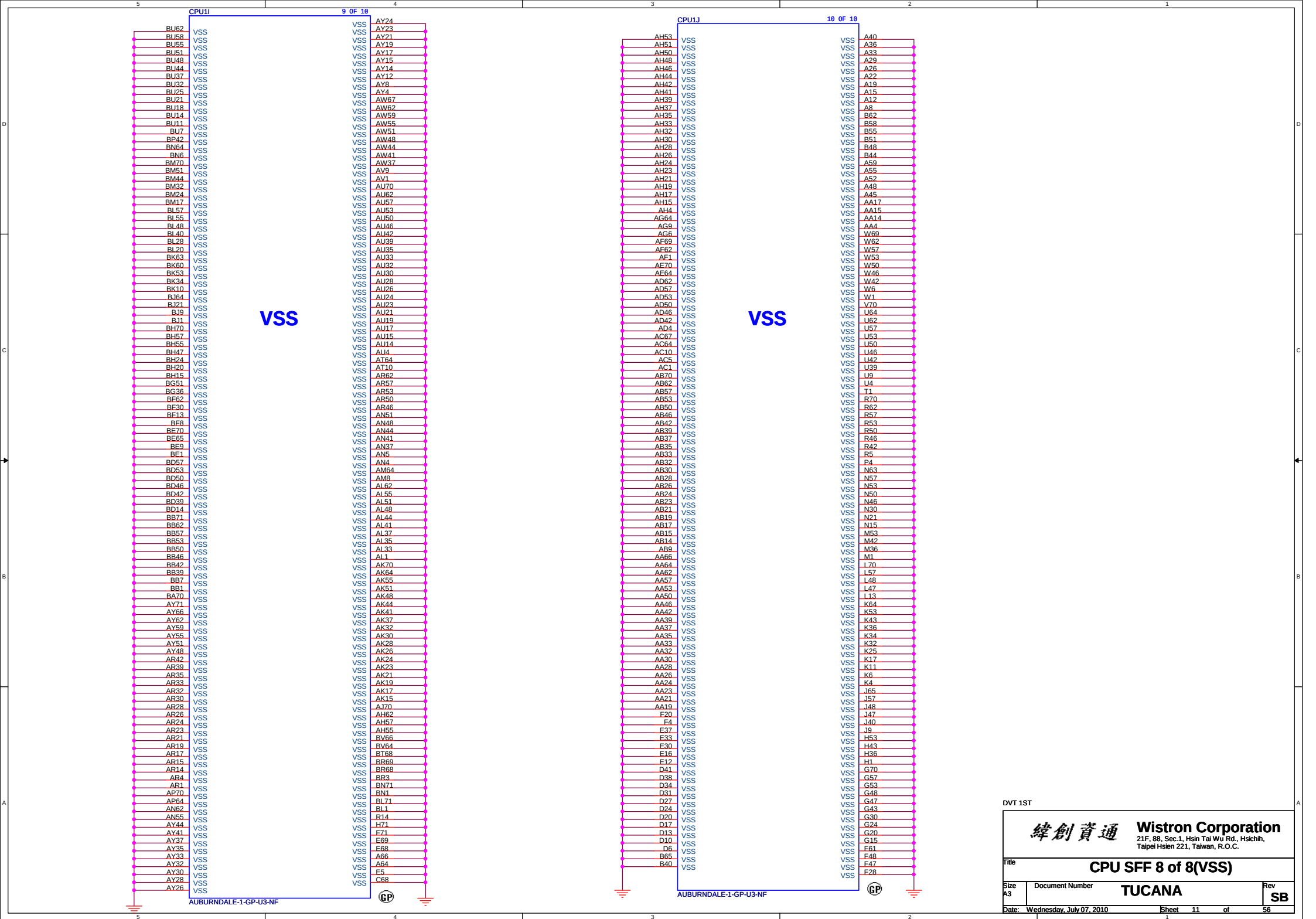
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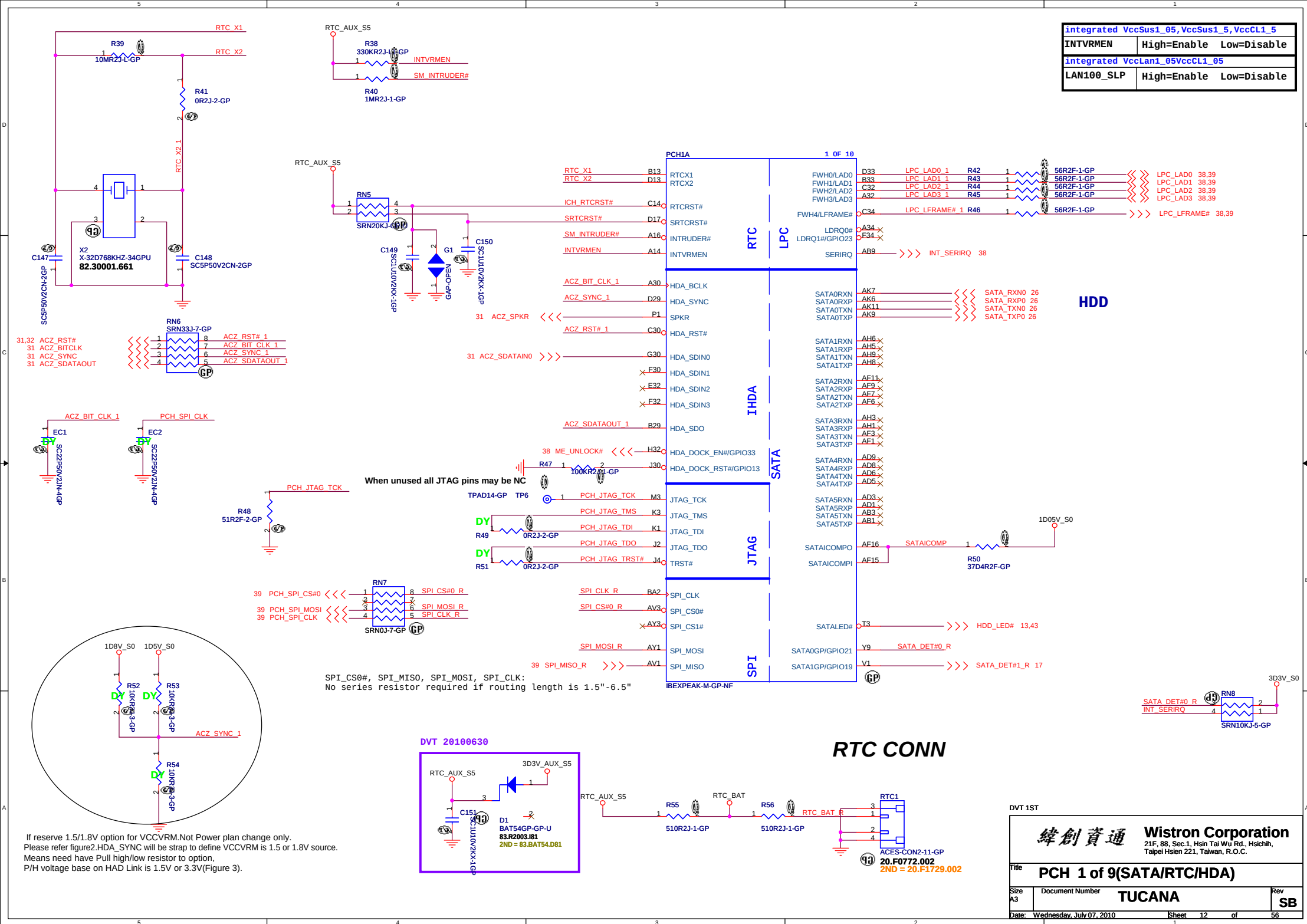


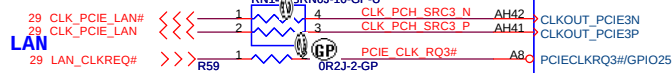
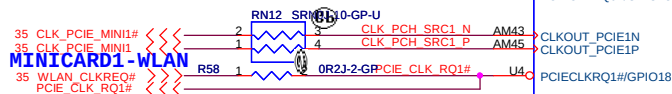
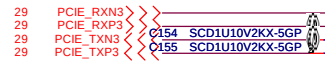
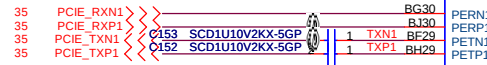




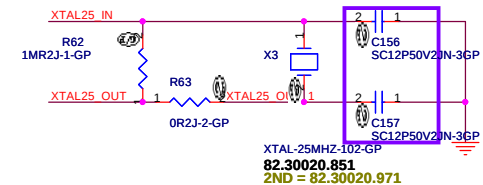
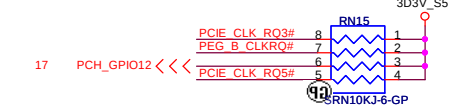
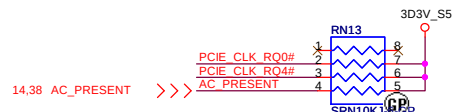
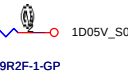
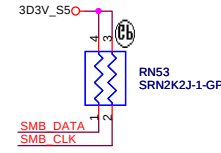
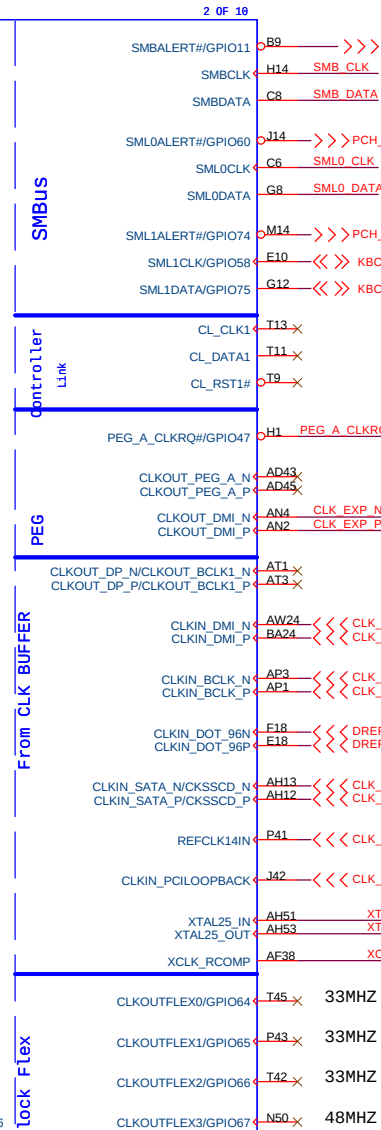
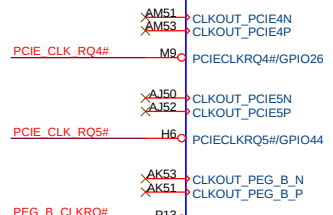
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CPU SFF 8 of 8(VSS)					
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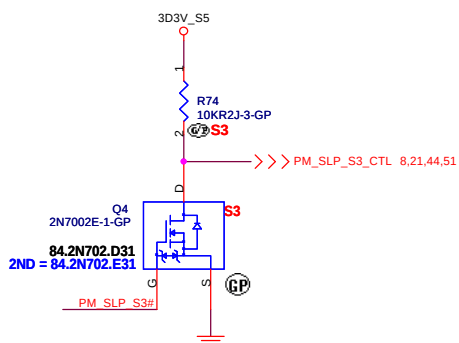
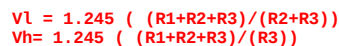
PCIECLKRQ{1,2} should have a 10K pull-up to +1.05VS (But CRB is pull-up to +3VS).



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Panel backlight enable control for LVDS -
used to gate power into the backlight circuit

3D3V_S0

RN19
SRN10K1-GP

RN20
SRN2K21-GP

R77
2K37R2F-GP

R78
150R2F-1-GP

R79
150R2F-1-GP

R80
150R2F-1-GP

R81
1K2D-1-GP

IBEXPEAK-M-GP-NF

PCH10D

PCH10F 18

LVDS

Digital Display Interface

CRT

23 PCH_BL_ON
23 PCH_LCDVDD_ON
23 L_BKLTCTL
23 CLK_DDC_EDID
23 DAT_DDC_EDID
23 LVDS_TXCLK-
23 LVDS_TXCLK+
23 LVDS_TXAOUT0-
23 LVDS_TXAOUT0+
23 LVDS_TXAOUT1-
23 LVDS_TXAOUT1+
23 LVDS_TXAOUT2-
23 LVDS_TXAOUT2+
24 CRT_BLUE
24 CRT_GREEN
24 CRT_RED
24 CRT_DDCCLK
24 CRT_DDCDATA
24 CRT_HSYNC
24 CRT_VSYNC
24 CRT_IREF

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B146
BG46
B148
BG48
BF45
BH45
T51
T53
BG44
B144
AU38
BD42
BC42
B142
BG42
BD40
BA40
AW38
BA38
Y49
AB49
BE44
BD44
AV40
BE40
BD40
BF41
BH41
BD38
BC38
BA38
U50
U52
BC46
BD46
AT38
B140
BG40
B138
BG38
BE37
BH37
BE36
BD36

PCH_HDMI_CLK 25
PCH_HDMI_DATA 25
PCH_HDMI_DETECT 25
PCH_HDMI_DATA2+_L 25
PCH_HDMI_DATA2+_L 25
PCH_HDMI_DATA1+_L 25
PCH_HDMI_DATA1+_L 25
PCH_HDMI_DATA0+_L 25
PCH_HDMI_CLK+_L 25

SB

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PCH 4 of 9(LVDS/CRT/DP)

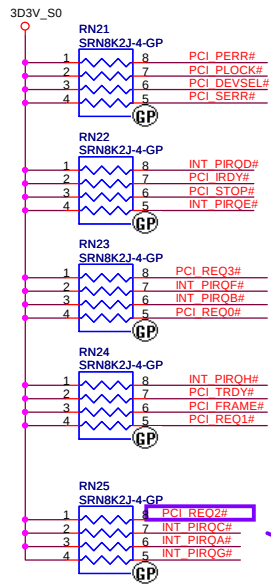
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Rev SB

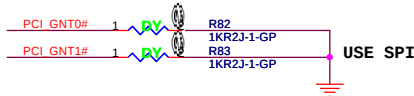
Date: Wednesday, July 07, 2010

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PCH 4 of 9(LVDS/CRT/DP)			
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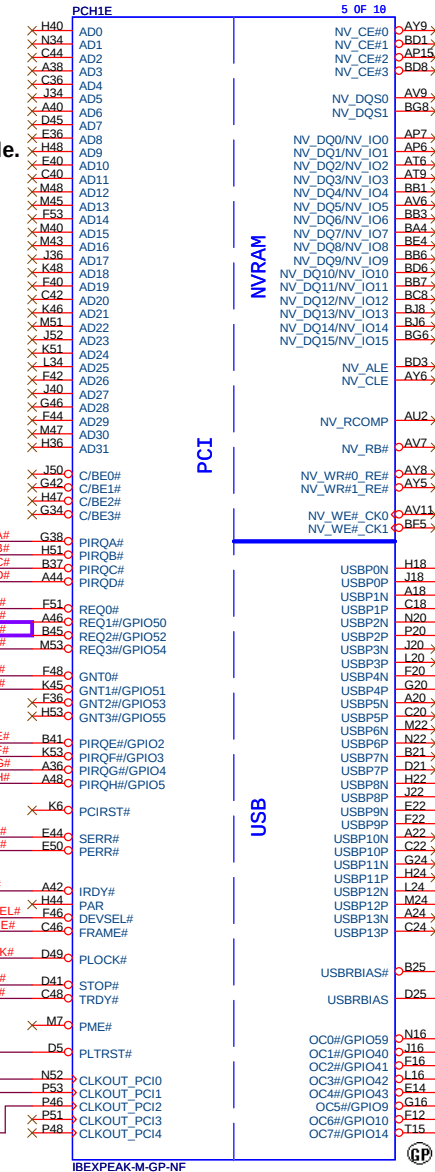
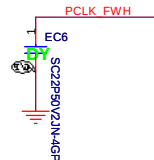
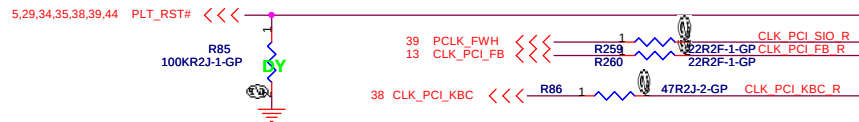


These pins are left as NC,
because the function is disable.



USE SPI

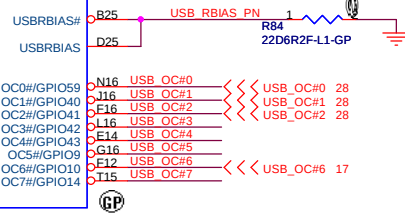
BOOT BIOS Strap		
PCI_GNT#0	PCI_GNT#1	BOOT BIOS Location
0	0	LPC(Default)
1	0	Reserved
0	1	PCI
1	1	SPI



These pins are left as NC,
because the function is disable.

USB Table

Pair	Device
0	External #0
1	External #1
2	CardReader
3	NC
4	External #2
5	NC
6	NC
7	NC
8	WLAN/WiMAX
9	CAMERA(HS)
10	NC
11	NC
12	BLUETOOTH(FS)
13	NC



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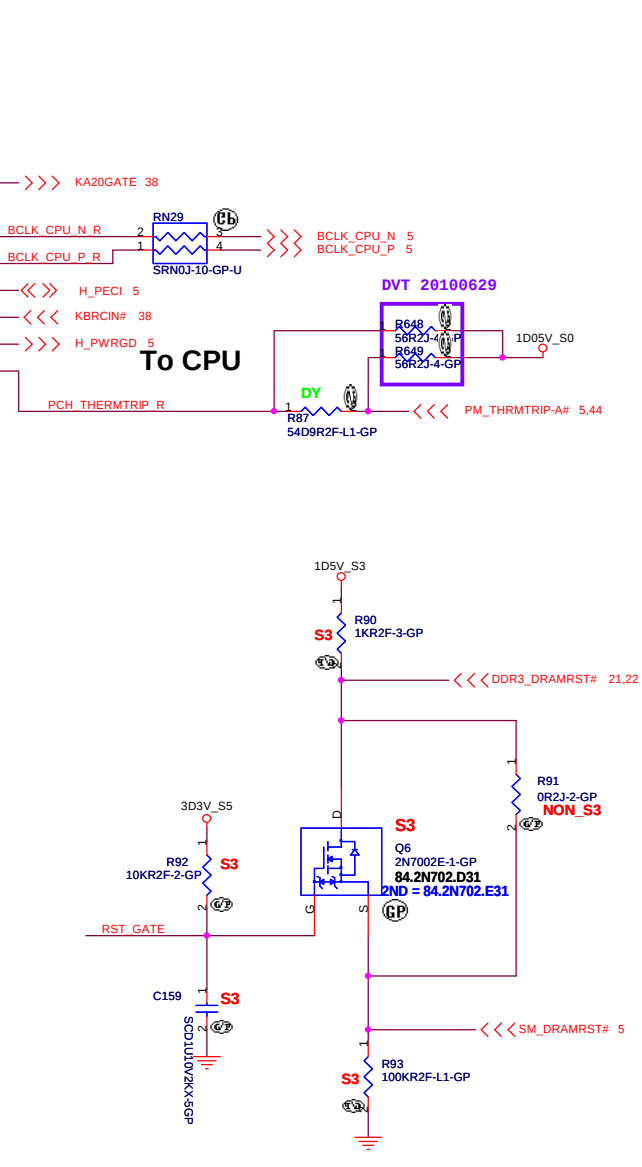
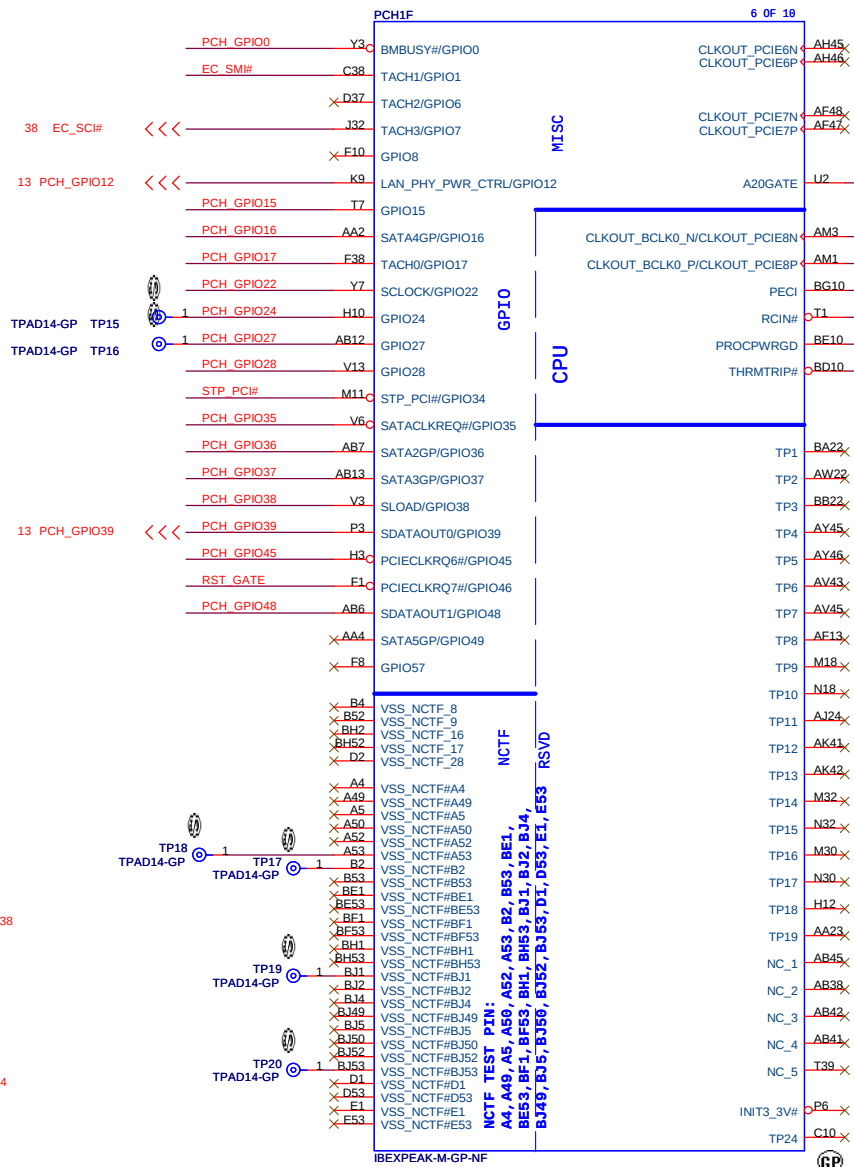
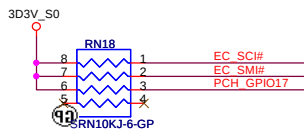
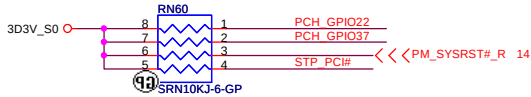
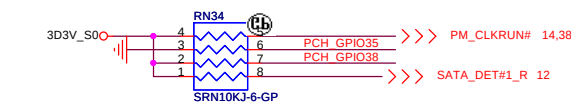
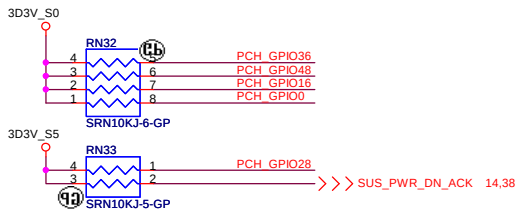
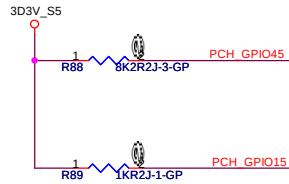
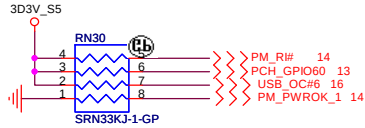
PCH 5 of 9(PCI/USB)		
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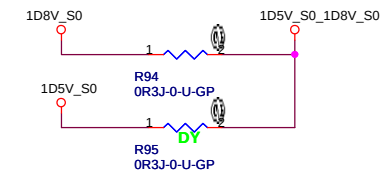
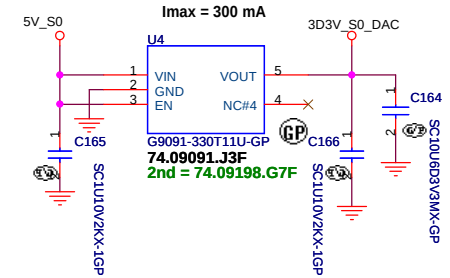
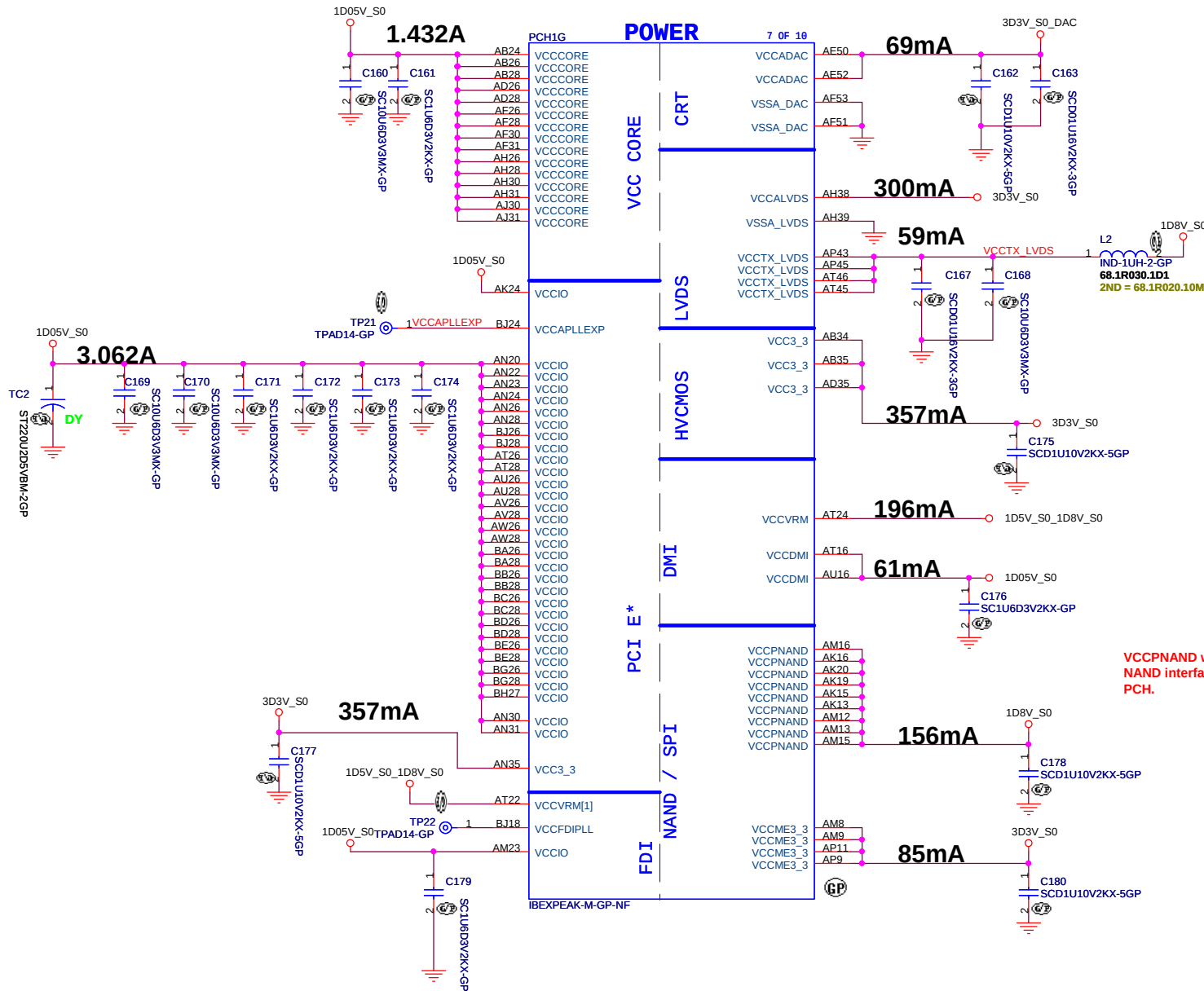
GPIO8 has a weak[20K] internal pull up.
No need to have external pull down/up.
GPIO8 pin set to high at reset.

GPIO15 has a weak[20K] internal pull down.
No need to have external pull up/down.
GPIO 15 pin is set to low at reset.

Low : ME Crypto TLS with no confidentiality
High : ME Crypto TLS with confidentiality

GPIO27 has a weak[20K] internal pull up.
To enable on-die PLL Voltage regulator,
should not place external pull down.





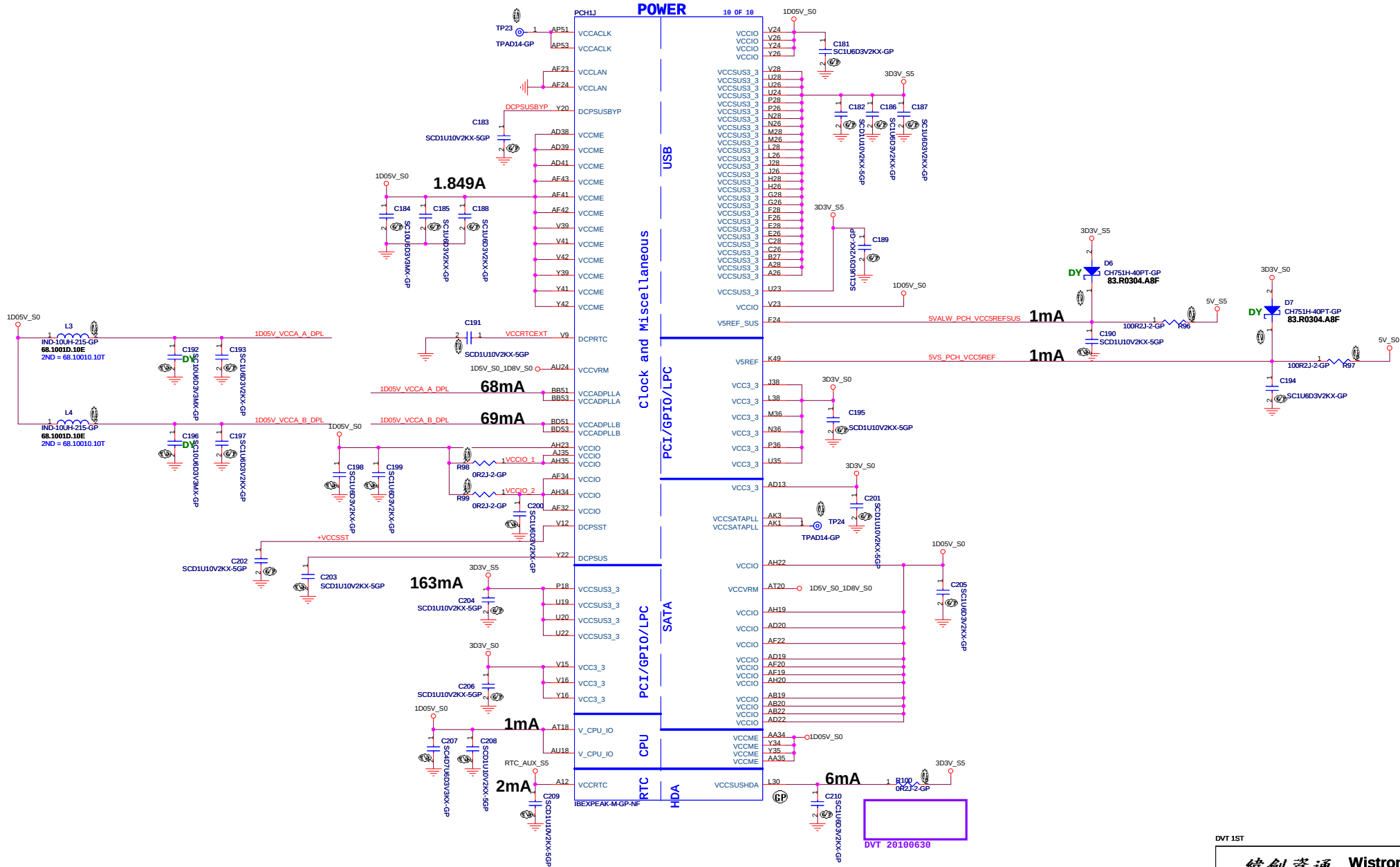
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Taipei Hsien 221, Taiwan, R.O.C.

Title **PCH 7 of 9(PWR/VCORE/LVDS)**

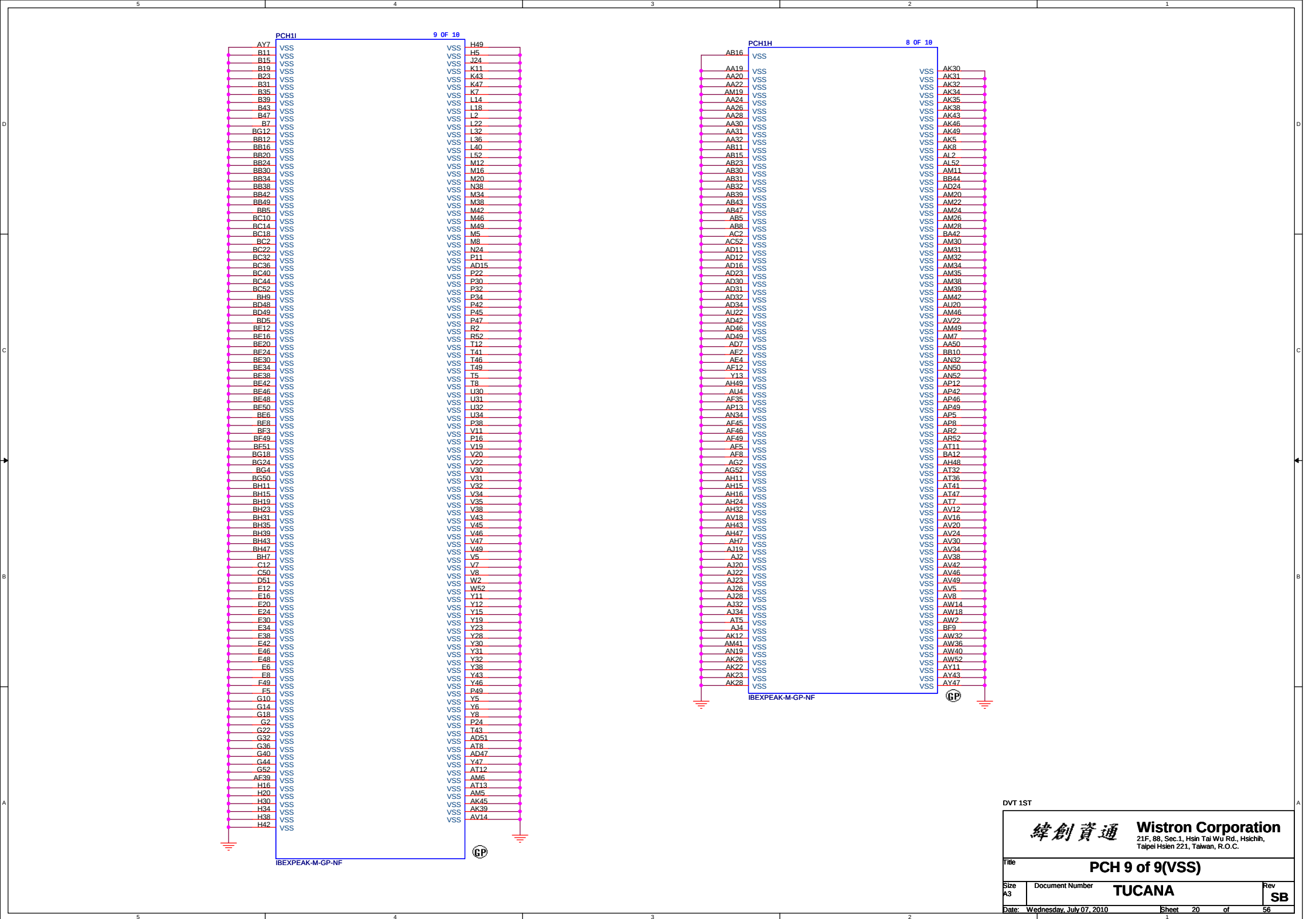
Size Custom Document Number **TUCANA** Rev **SB**

Date: Wednesday, July 07, 2010 Sheet 18 of 56



DVT 1ST

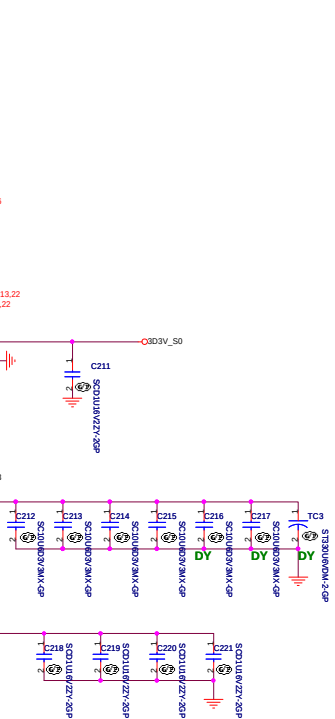
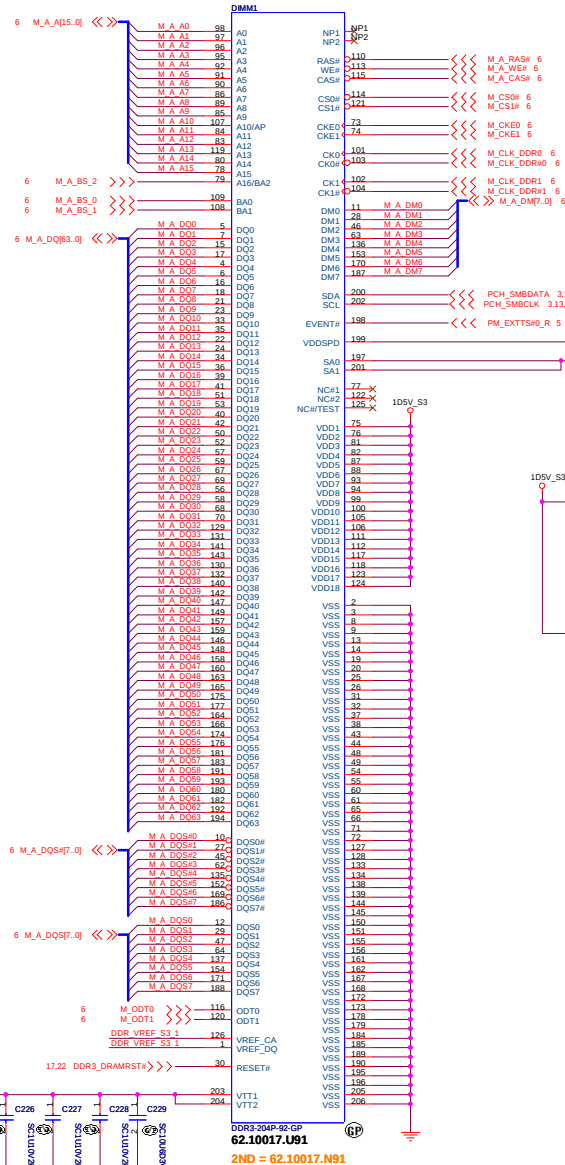
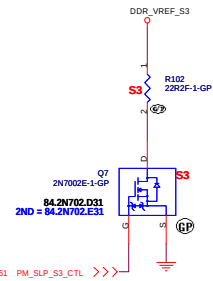
緯創資通		Wistron Corporation	
		21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.	
Title PCH 8 of 9 (PWRISATAIUSB)			
Size Custom	Document Number	TUCANA	Rev SB
Date: Wednesday, July 07, 2010		Sheet 19 of	56



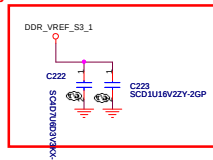
DVT 1ST

緯創資通		Wistron Corporation	
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.			
Title PCH 9 of 9(VSS)			
Size A3	Document Number TUCANA	Rev SB	
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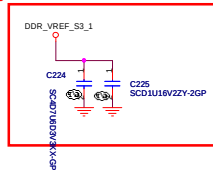
DDR3 SOCKET_1



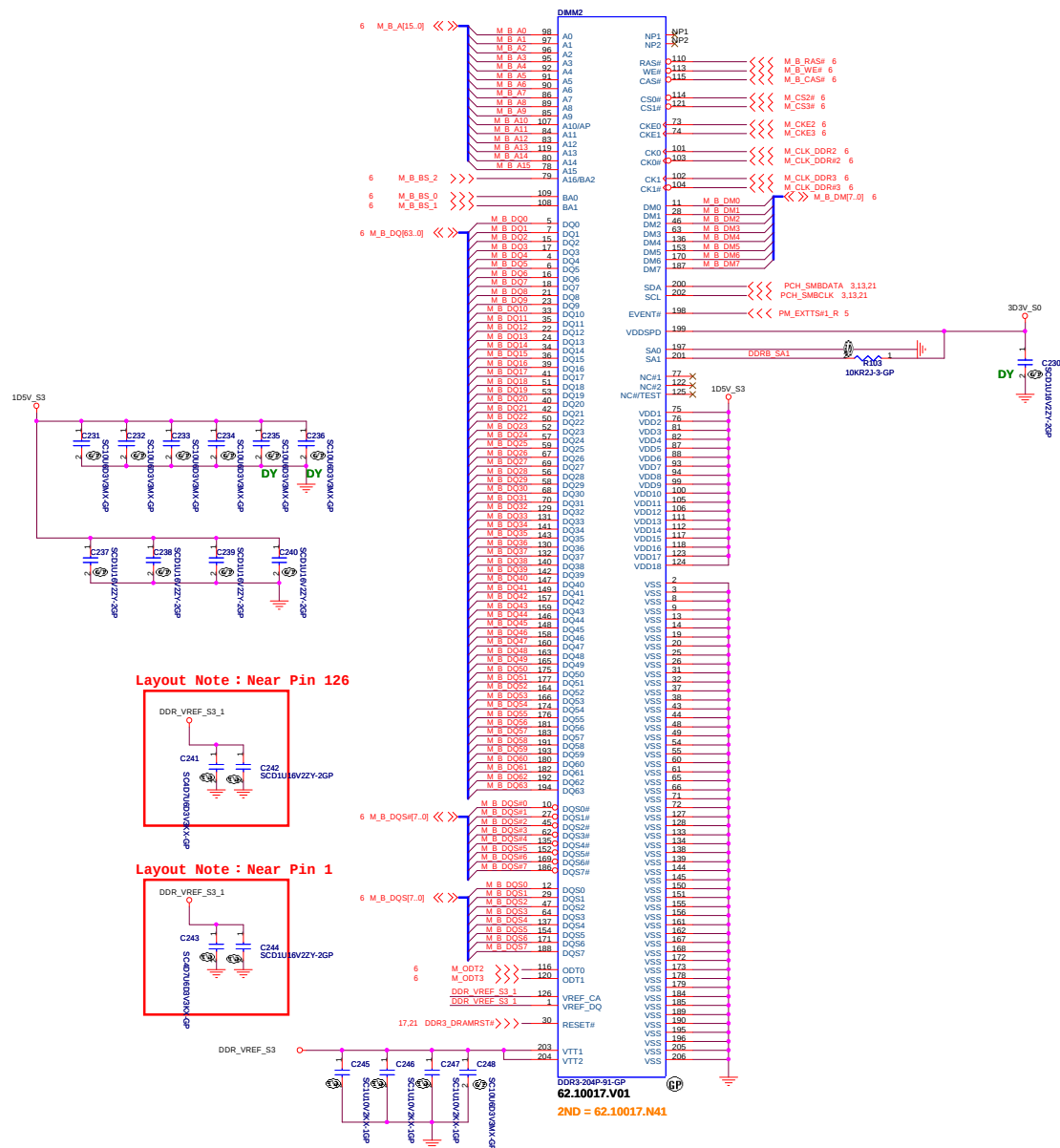
Layout Note : Near Pin 126



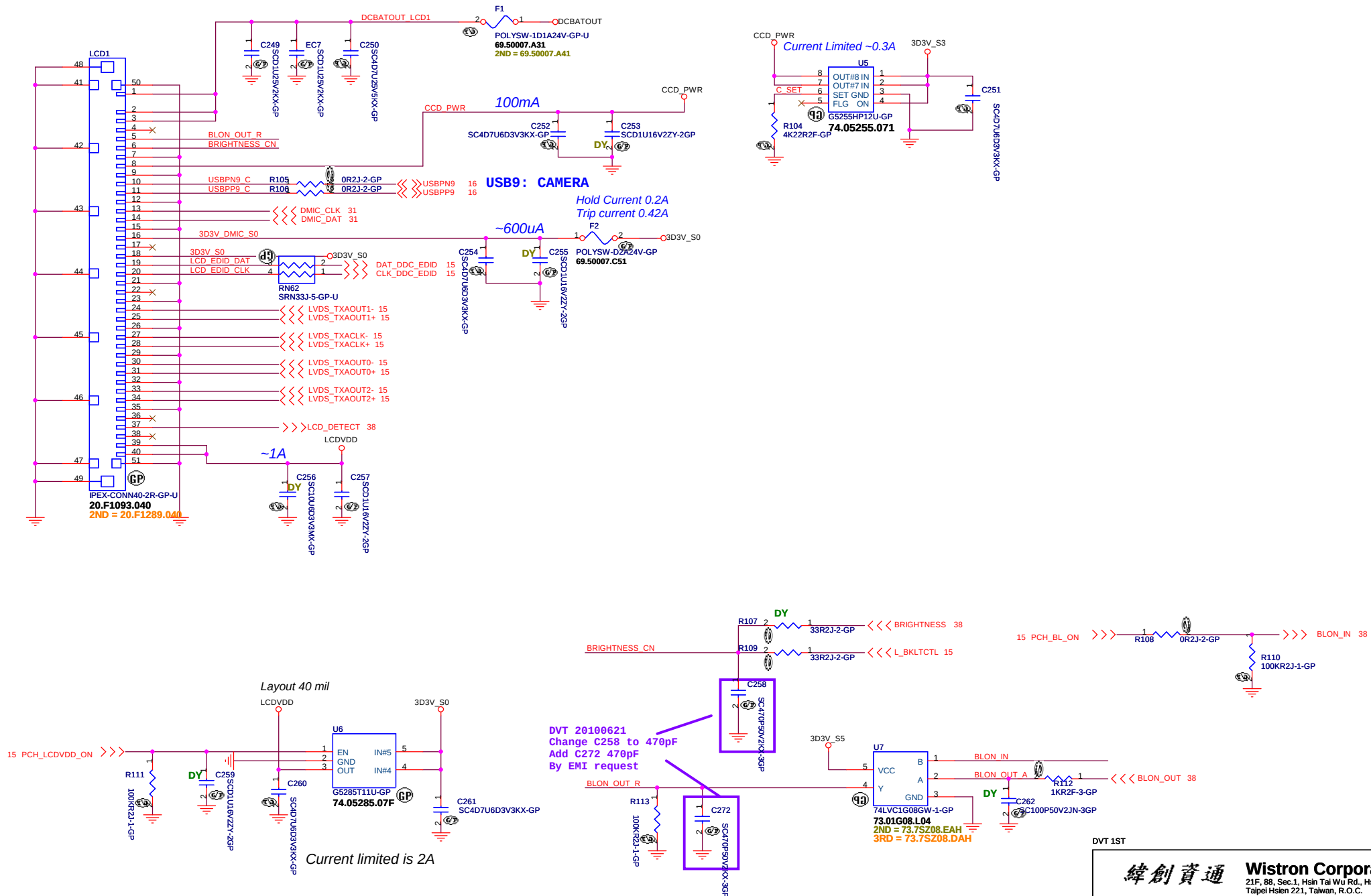
Layout Note : Near Pin 1



DDR3 SOCKET_2



LCD/CCD CONN



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Title

LCD CONN

Size	Document Number
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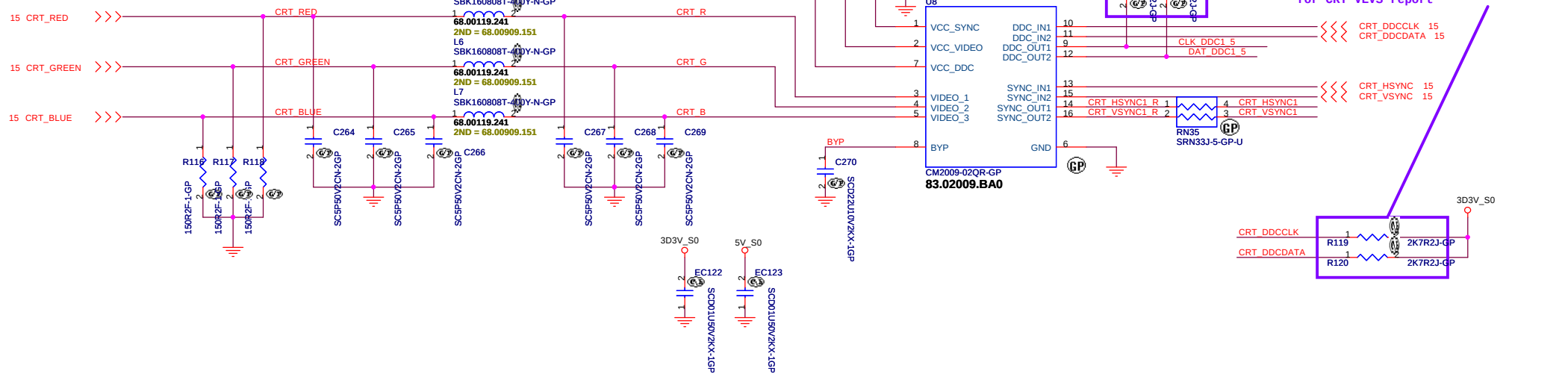
TUCANA

Date: Wednesday, July 07, 2010

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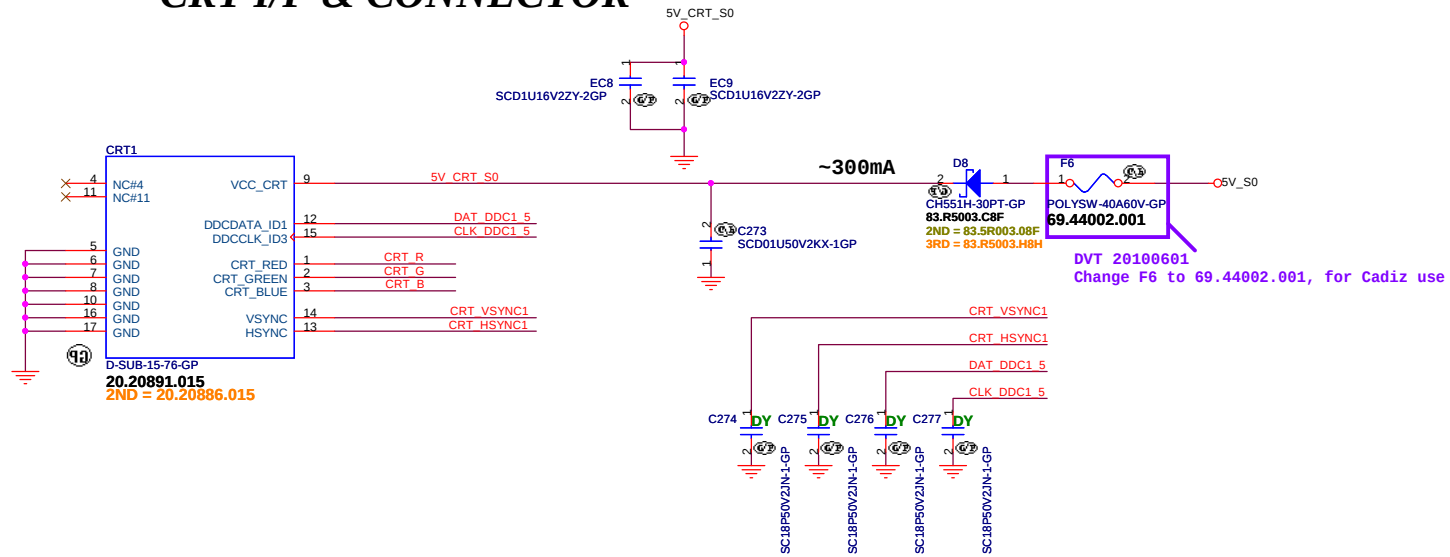
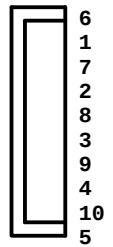
Layout Note:
Place these resistors
close to the CRT-out
connector

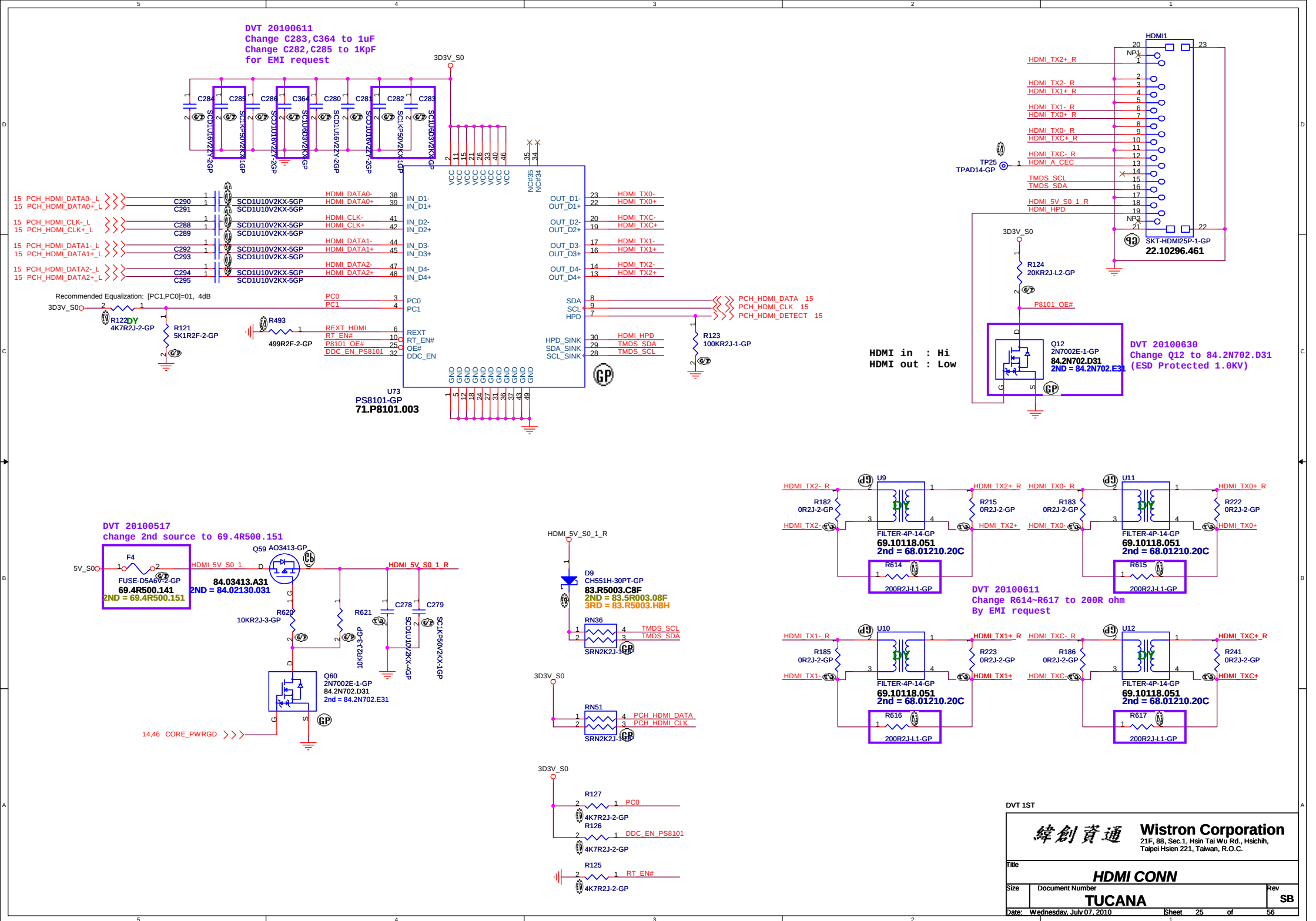
Ferrite bead impedance: 40 ohm@100MHz



Layout Note:
* Must be a ground return path between this ground and the ground on the VGA connector.
Pi-filter & 150 Ohm pull-down resistors should be as close as to CRT CONN. RGB will hit 75 Ohm first, pi-filter, then CRT CONN.

CRT I/F & CONNECTOR

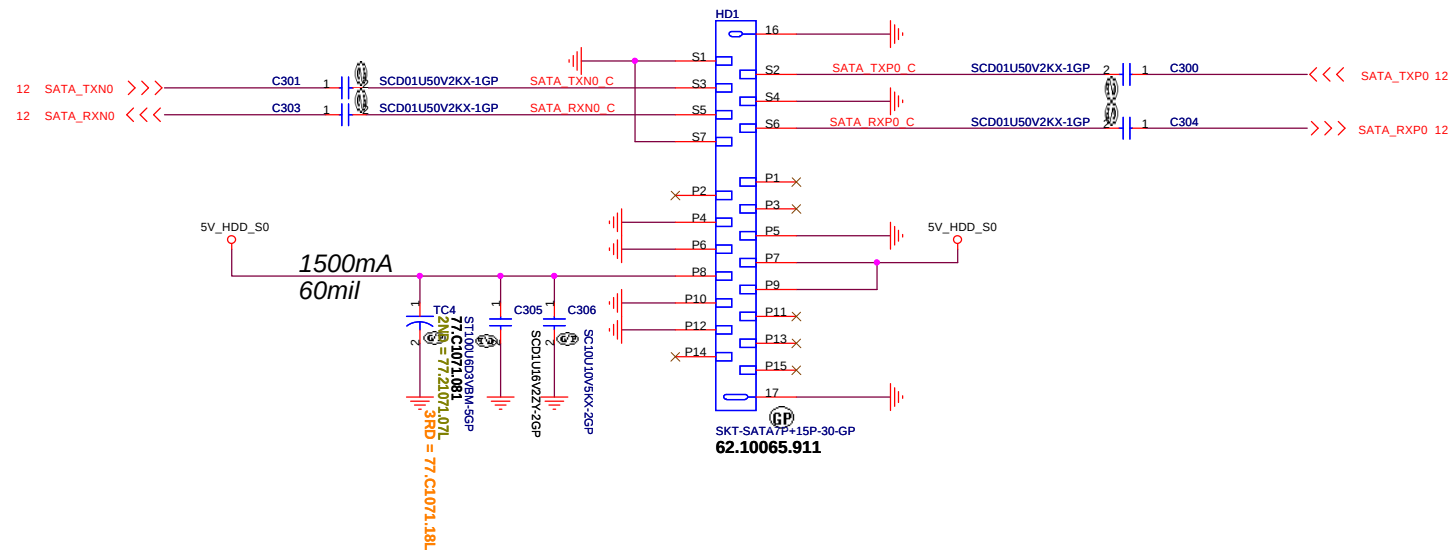






DVT 20100524
Change R148 to 3.3K ohm
add C437 0.1uF

SSD SATA Connector

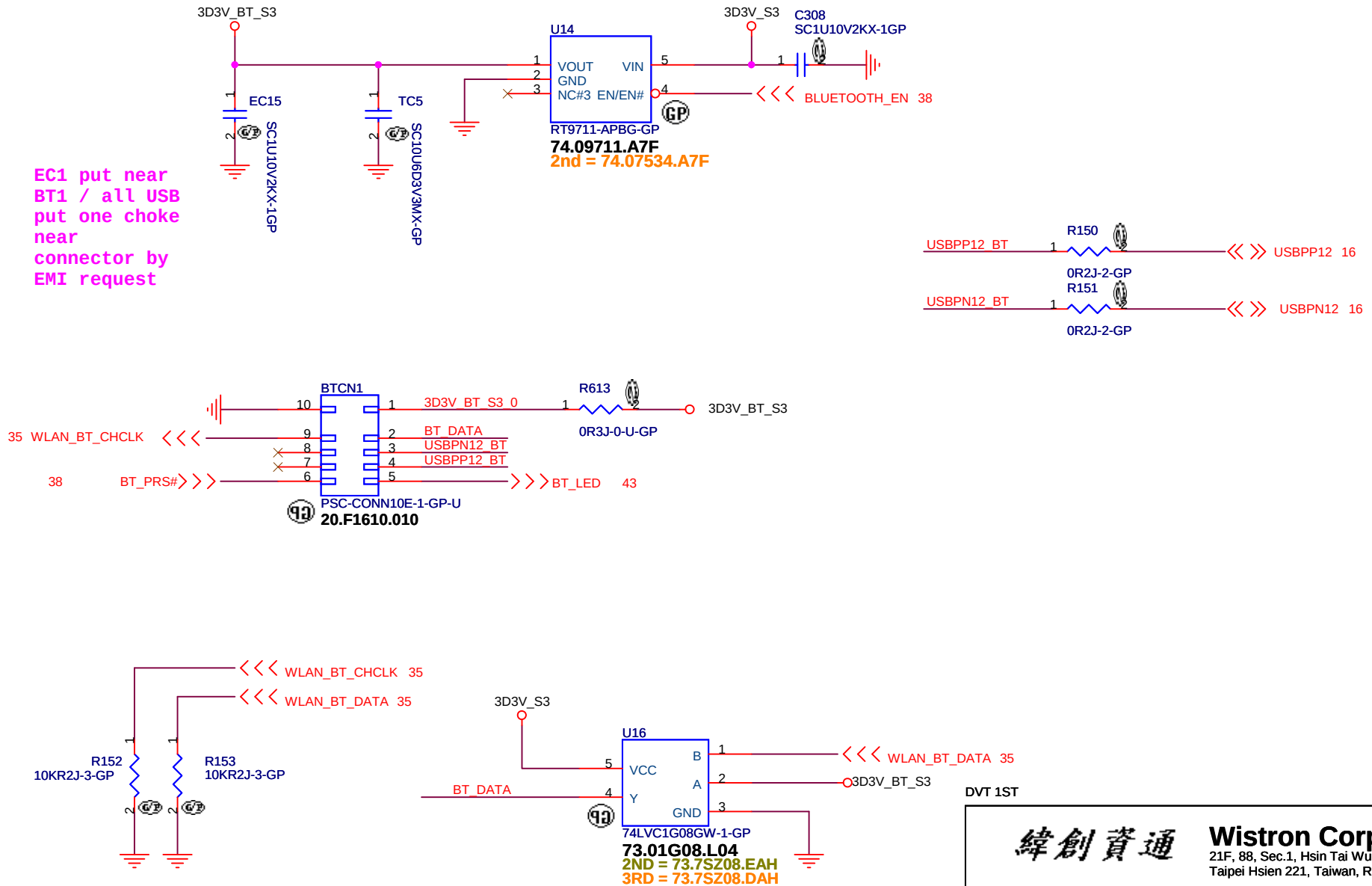


<Core Design>

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Taipei Hsien 221, Taiwan, R.O.C.

Bluetooth

EC1 put near
BT1 / all USB
put one choke
near
connector by
EMI request



DVT 1ST

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Taipei Hsien 221, Taiwan, R.O.C.

Title

Bluetooth

Size

Document Number

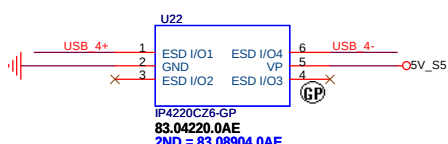
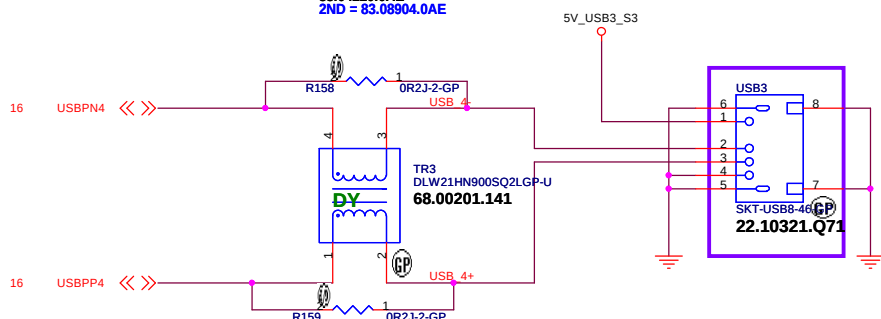
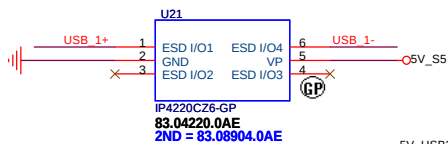
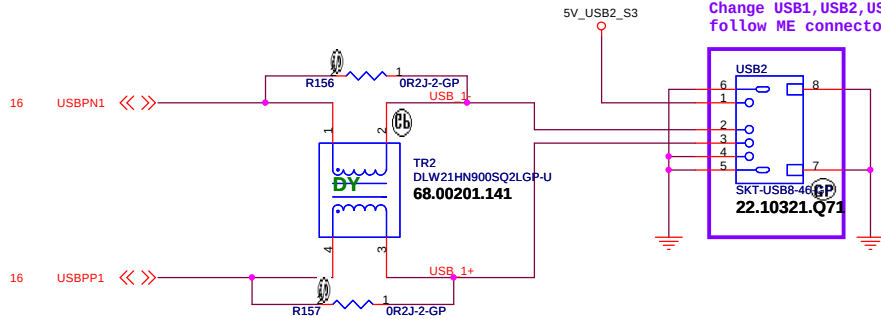
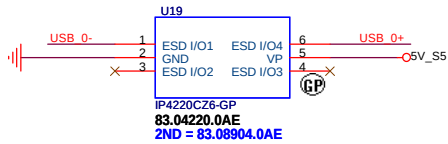
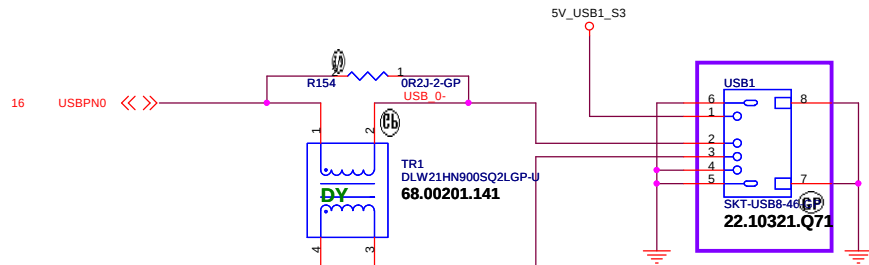
TUCANA

Rev

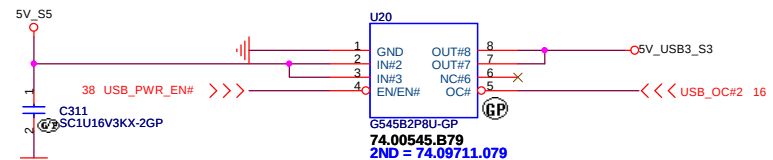
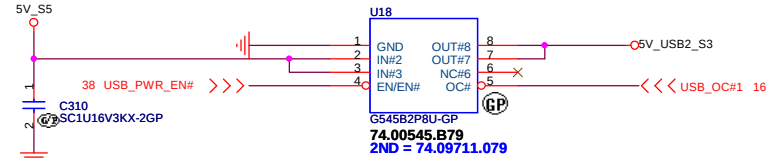
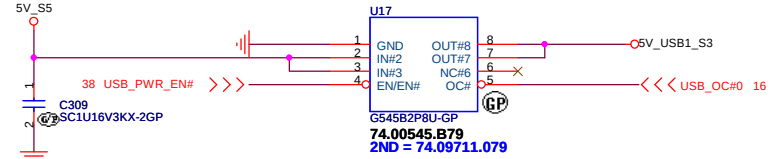
SB

Date: Wednesday, July 07, 2010

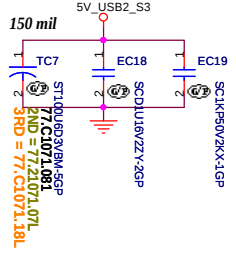
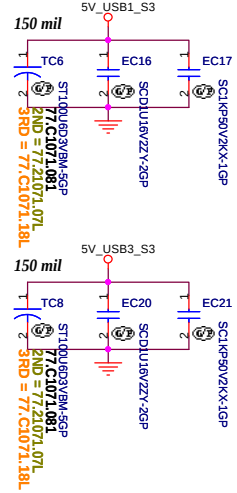
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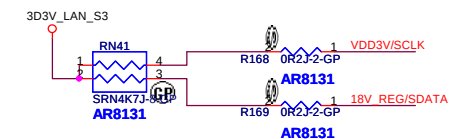
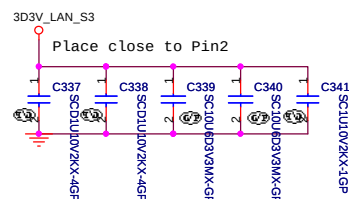
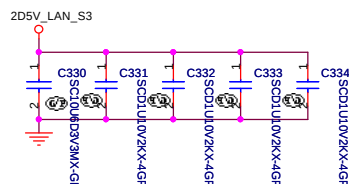
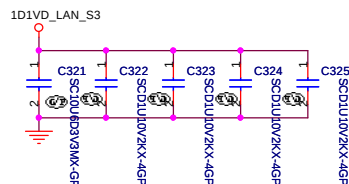
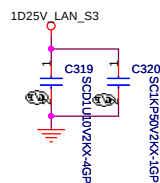
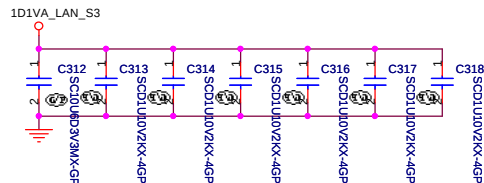


DVT 20100604
Change USB1,USB2,USB3 to 22.10321.Q71
follow ME connector list.

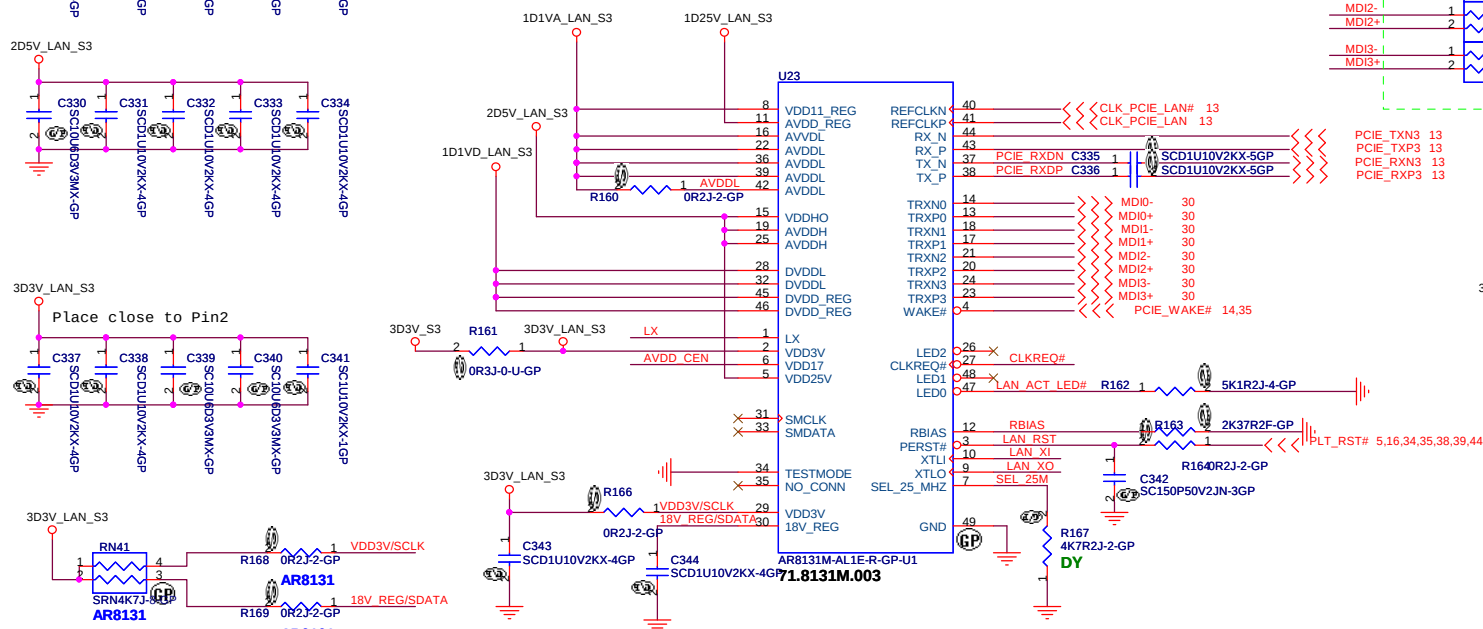
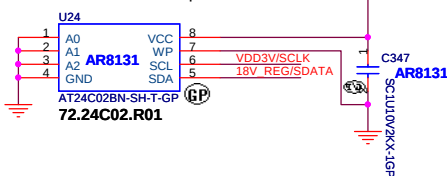


U17,U18,U20 Current Limit 1.5A

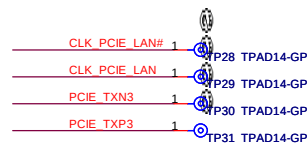




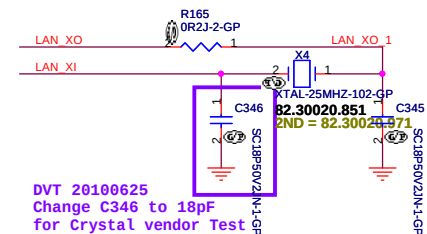
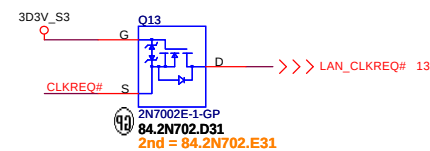
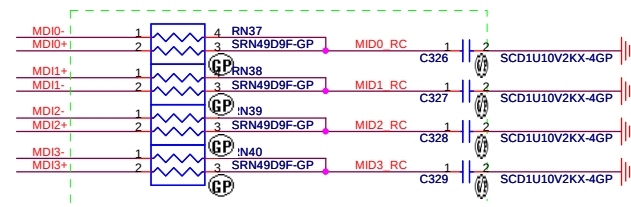
for AR8131 chip



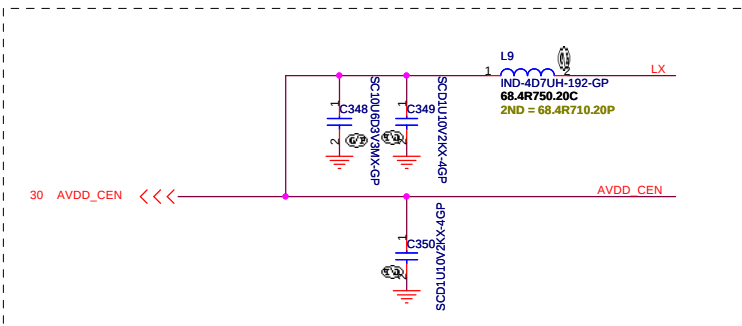
For AR8131: RN41,R168,R169,U24,C347 are need to stuff.
For AR8131M: RN41,R168,R169,U24,C347 are DY



Close to LAN_AR8131



DVT 20100625
Change C346 to 18pF
for Crystal vendor Test



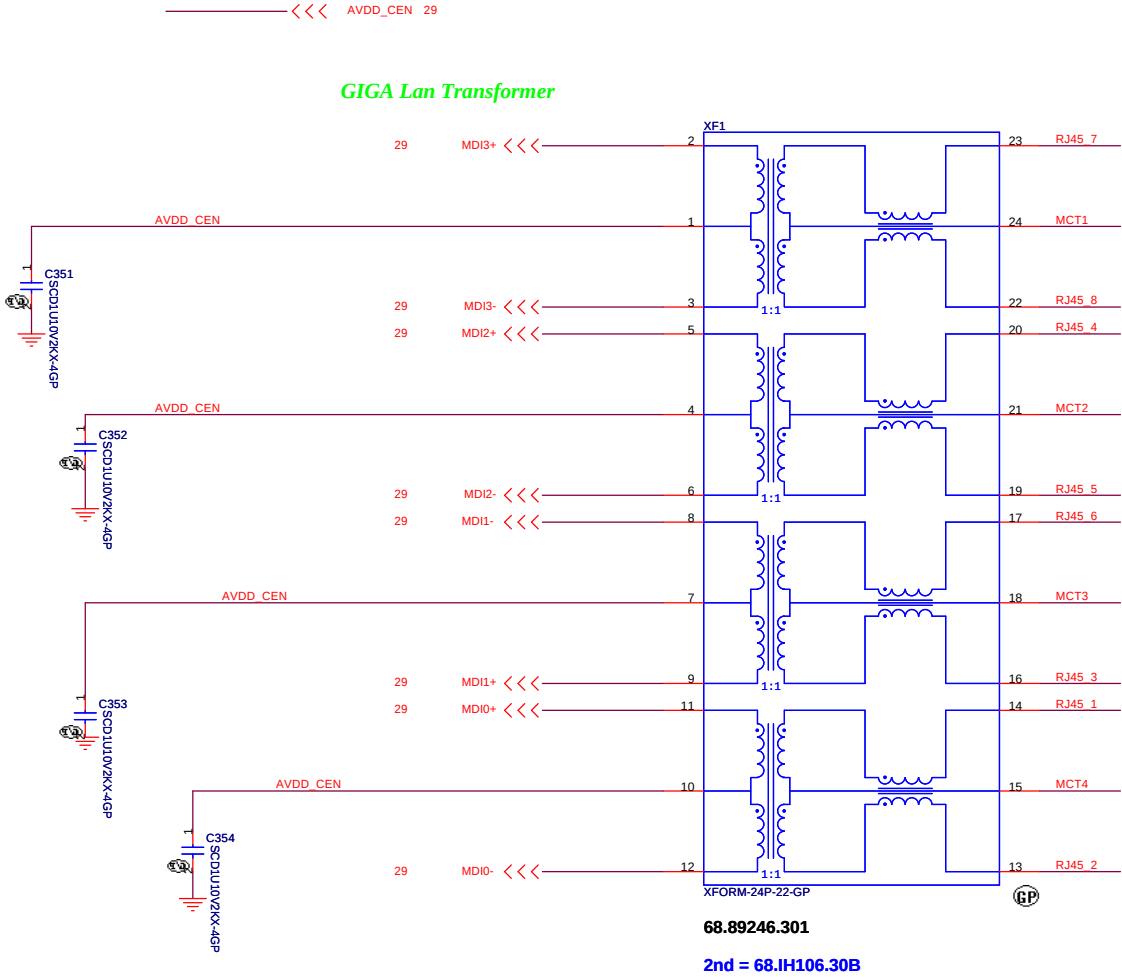
Close to U3

DVT 1ST

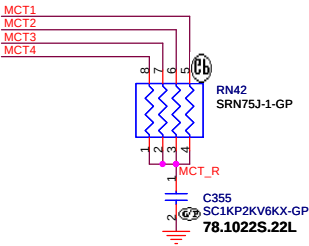
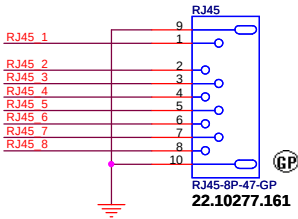
- 1.route on bottom as differential pairs.
- 2.Tx+/Tx- are pairs. Rx+/Rx- are pairs.
- 3.No vias, No 90 degree bends.
- 4.pairs must be equal lengths.
- 5.6mil trace width,12mil separation.
- 6.36mil between pairs and any other trace.
- 7.Must not cross ground moat,except RJ-45 moat.

LAN Transformer

GIGA Lan Transformer

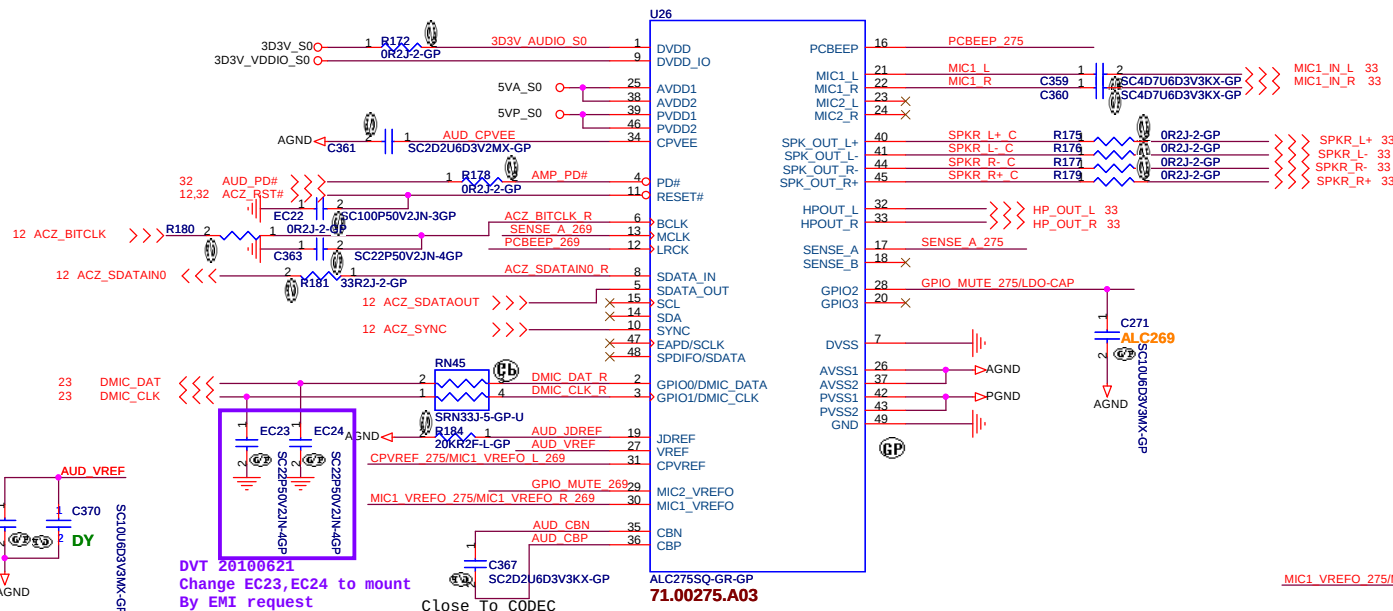
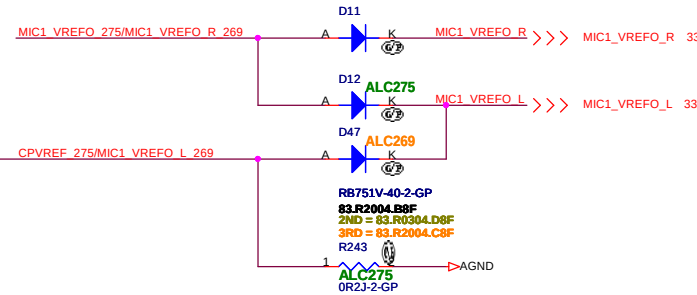
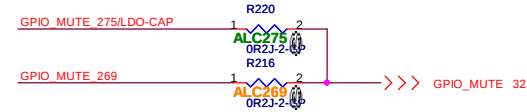
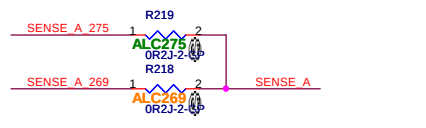
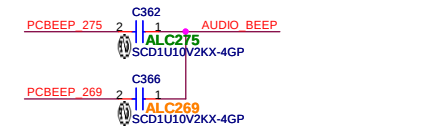
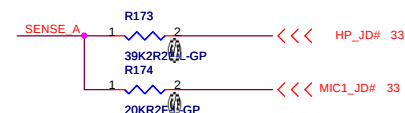
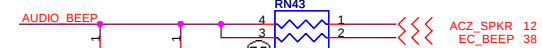
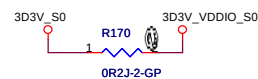


LAN Connector

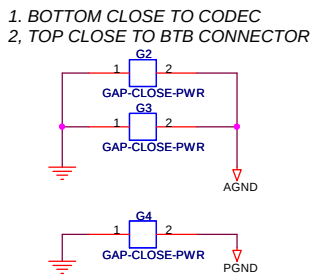
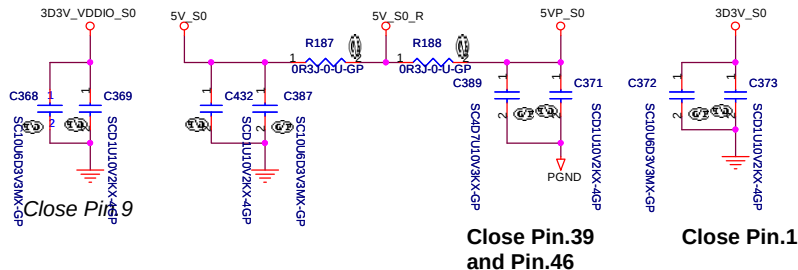


DVT 1ST

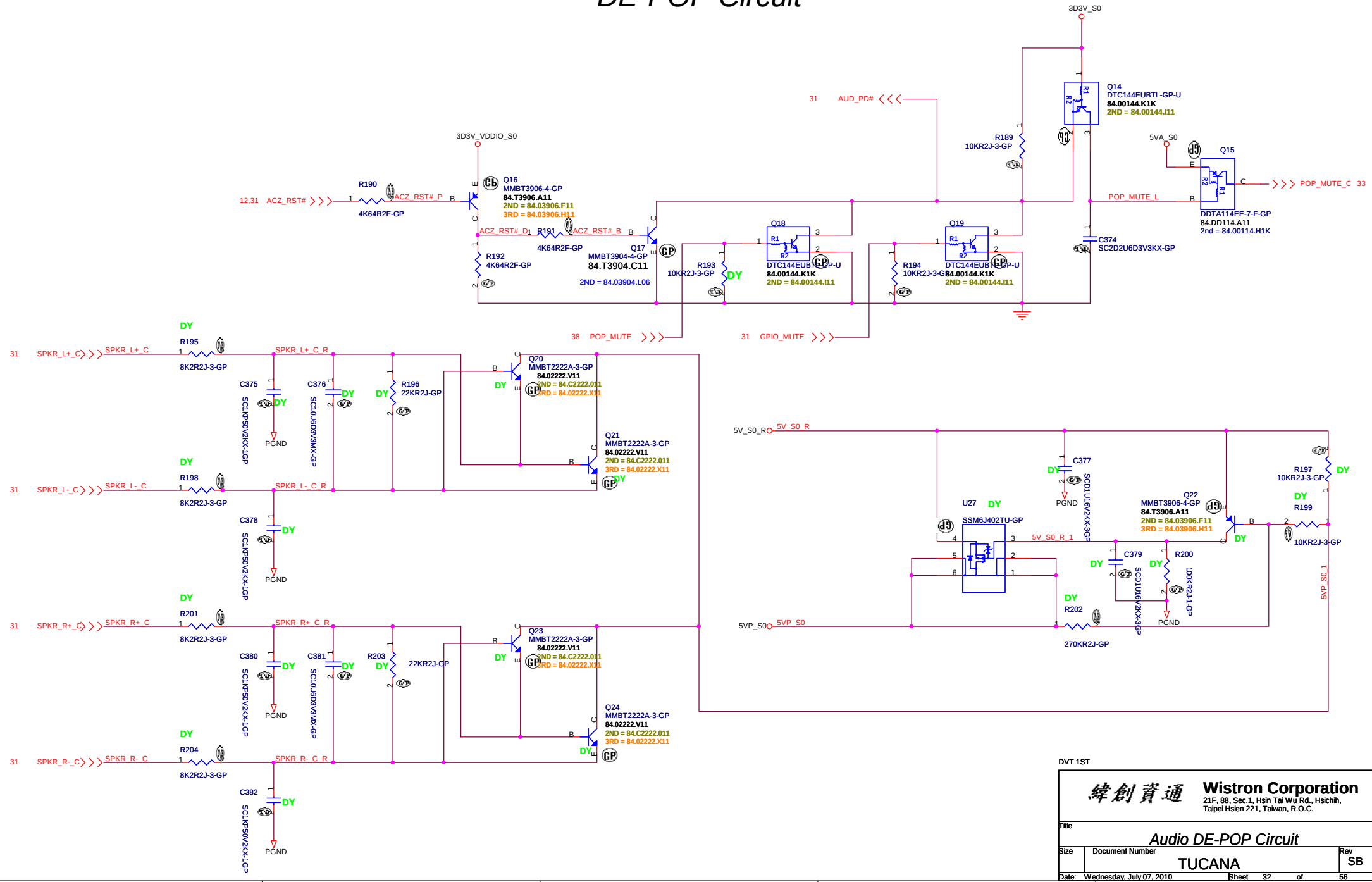
緯創資通		Wistron Corporation	
		21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.	
Title			
LAN CONN			
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Tucana use ALC269-VB5
71.00269.E03



DE-POP Circuit

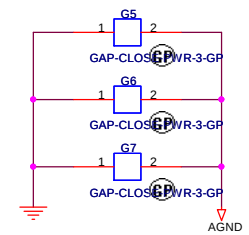
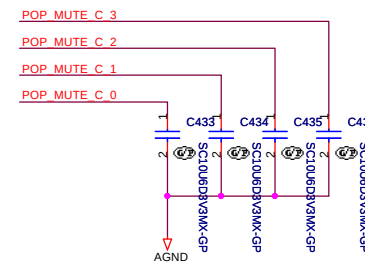
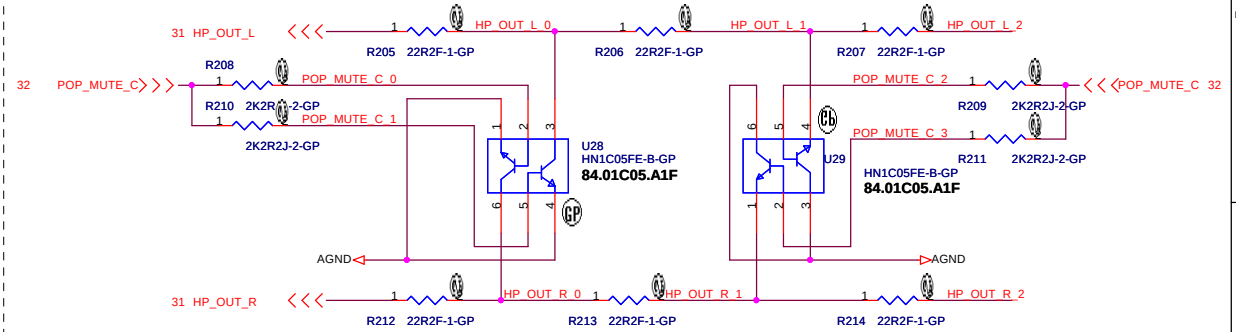
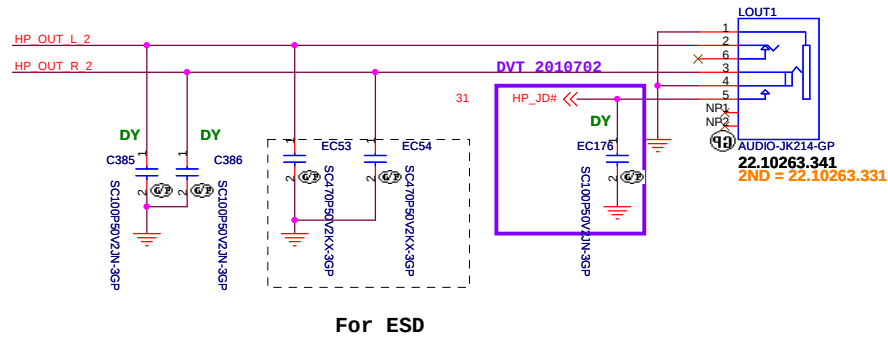


DVT 1ST

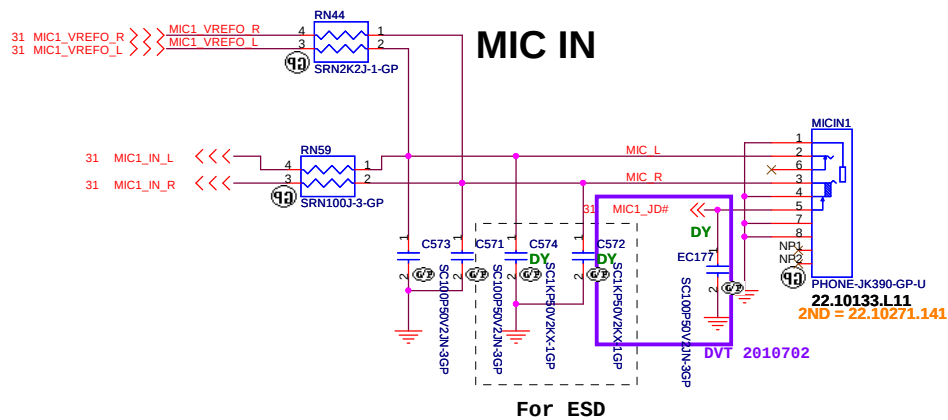
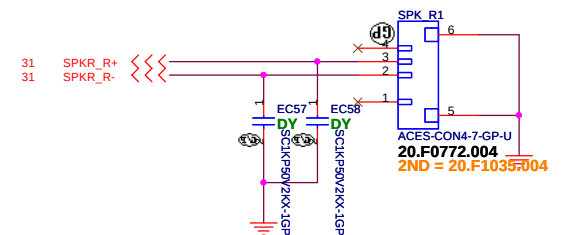
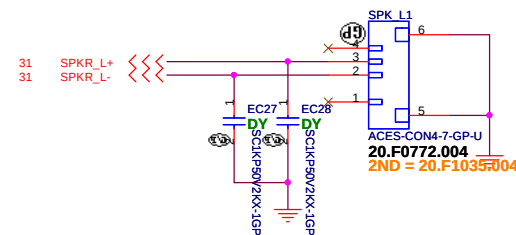
緯創資通 Wistron Corporation
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih,
Taipei Hsien 221, Taiwan, R.O.C.

Title			
Audio DE-POP Circuit			
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LINE OUT



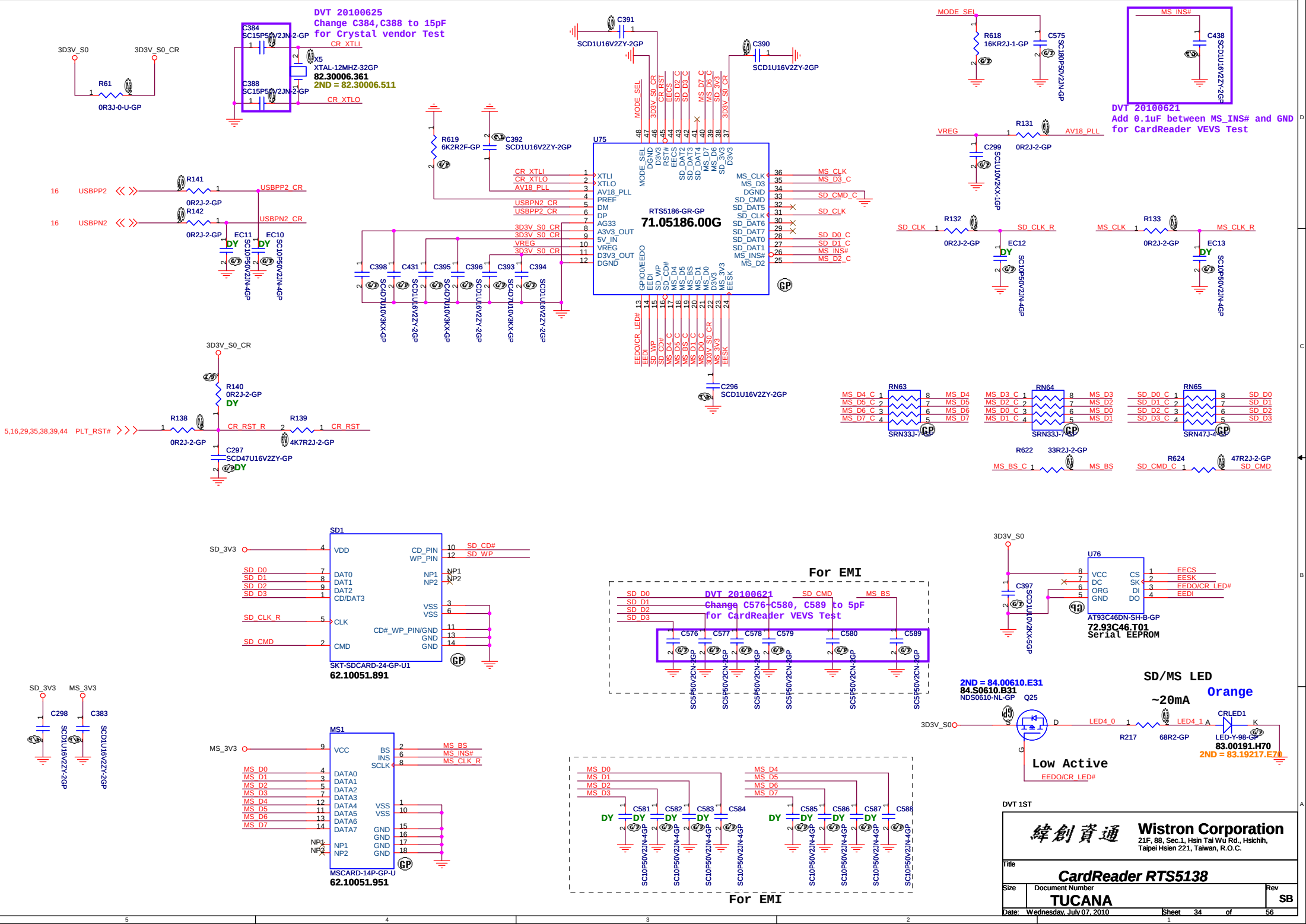
Internal Speaker CONN



DVT 1ST

緯創資通 Wistron Corporation
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Taipei Hsien 221, Taiwan, R.O.C.

Title		
Audio Jack & Speaker		
Size	Document Number	Rev
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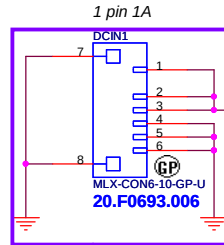


1

Place near MINI1

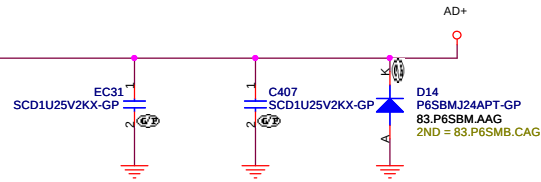


DC IN Connector



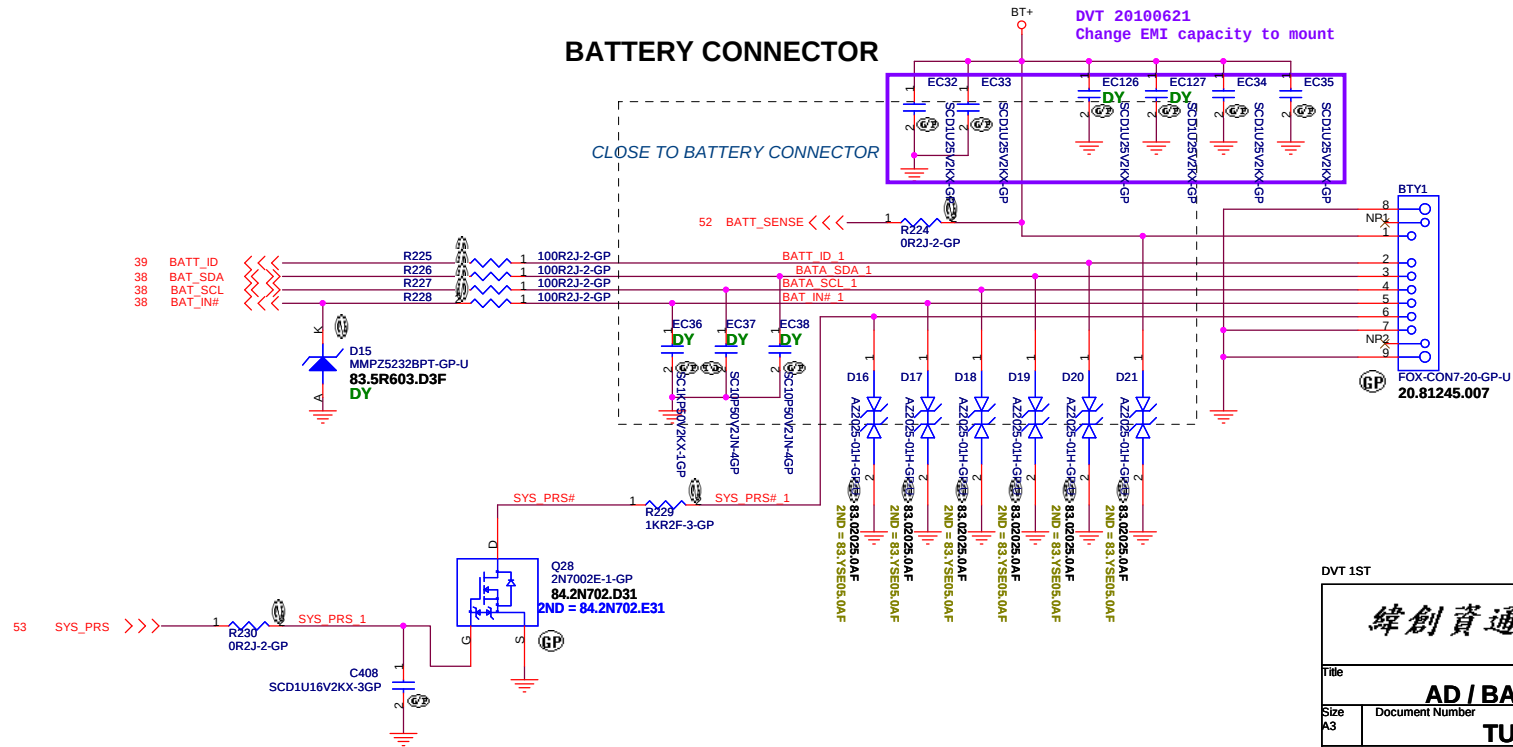
DVT 20100610
Change DCIN1 to 20.F0693.006
(follow connector list)

Adaptor in to generate DCBATOUT



BATTERY CONNECTOR

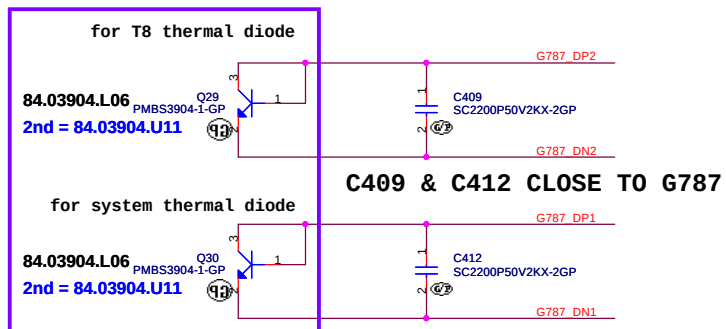
CLOSE TO BATTERY CONNECTOR



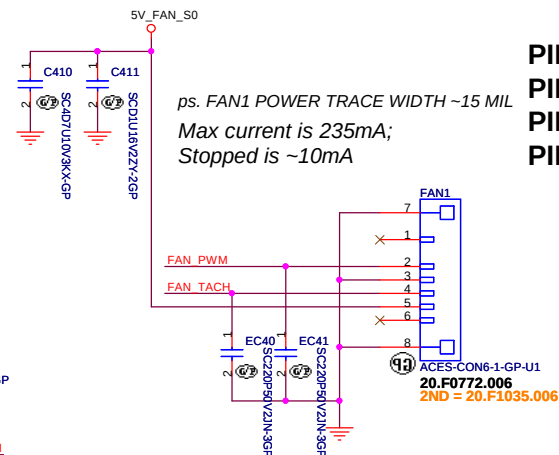
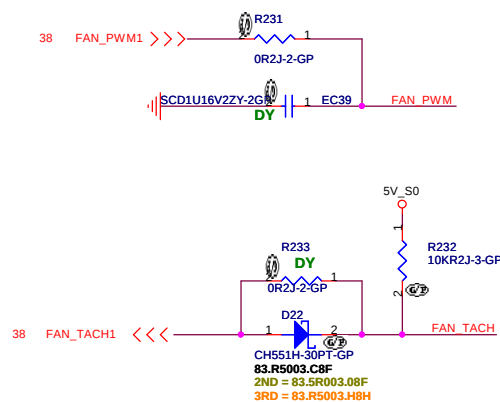
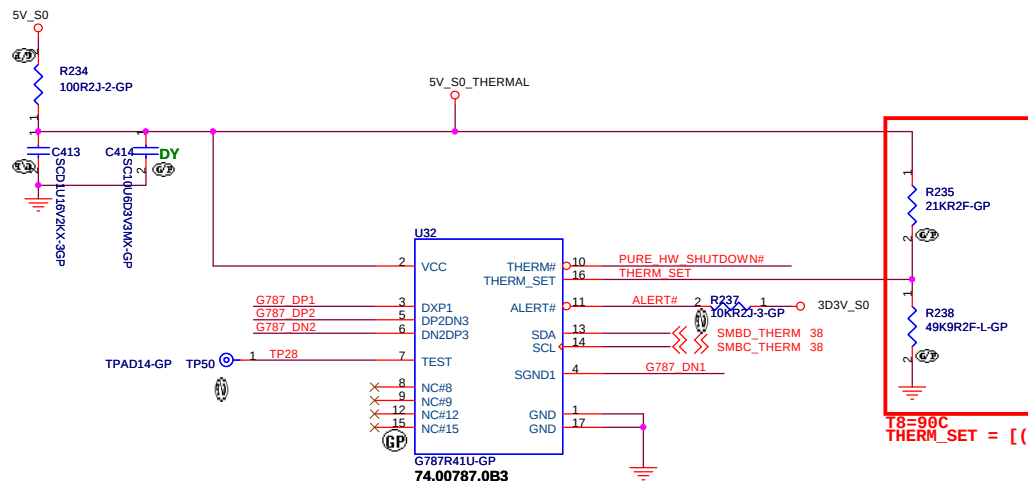
DVT 1ST

緯創資通 Wistron Corporation
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih,
Taipei Hsien 221, Taiwan, R.O.C.

Title			AD / BATT CONN	
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A3		TUCANA		SB
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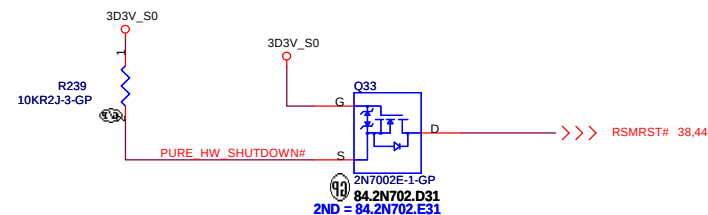
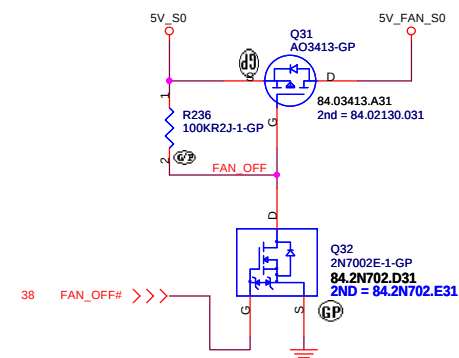


DVT 20100705
Delete Q29,Q30 main source 84.T3904.C11, follow CARAVEL-CP design



PWM FAN

PIN1 PWM
PIN2 GND
PIN3 FG
PIN4 VCC



DVT 1ST

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Taipei Hsien 221, Taiwan, R.O.C.

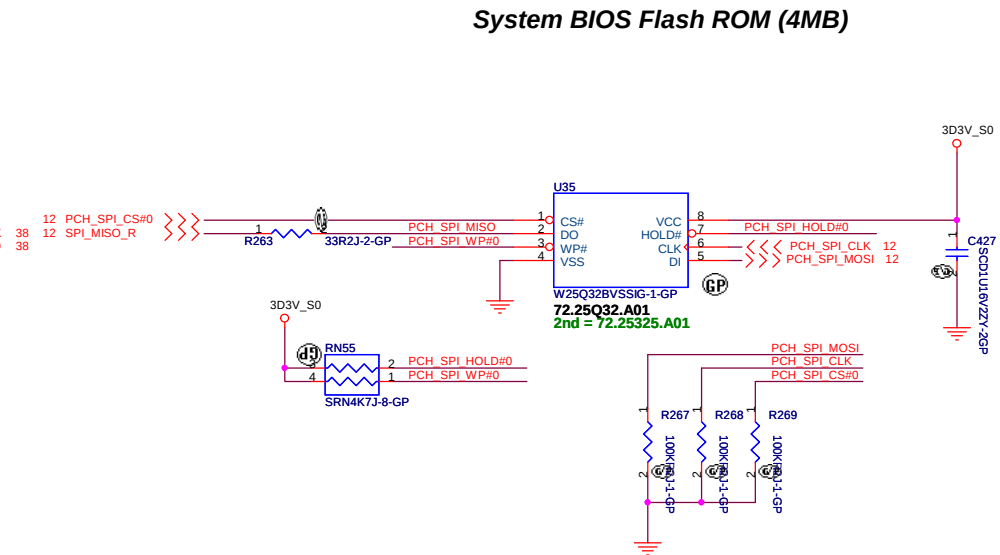
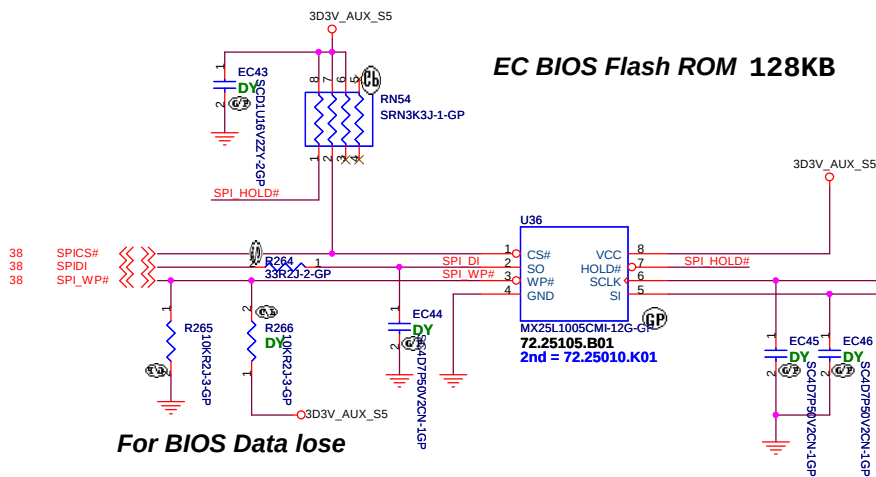
Title
Size Document Number
Date: Wednesday, July 07, 2010

Thermal/Fan Controller

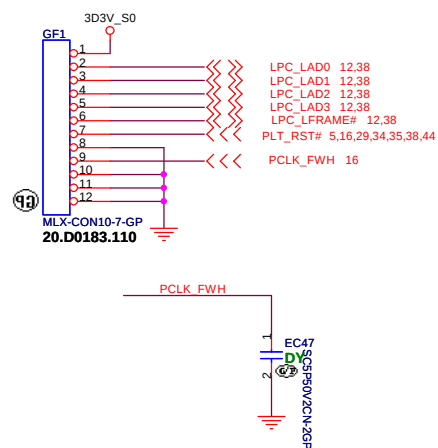
TUCANA

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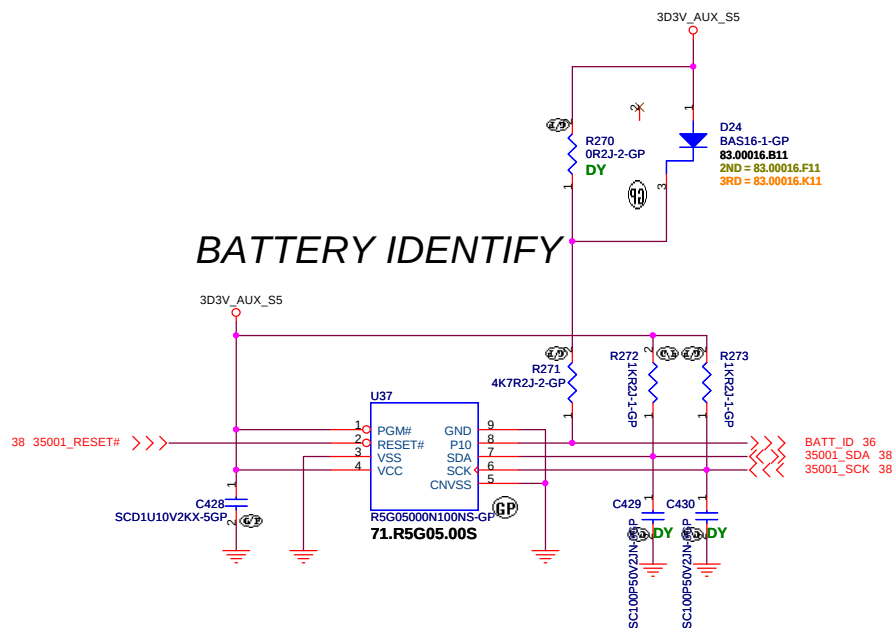
Rev
SB

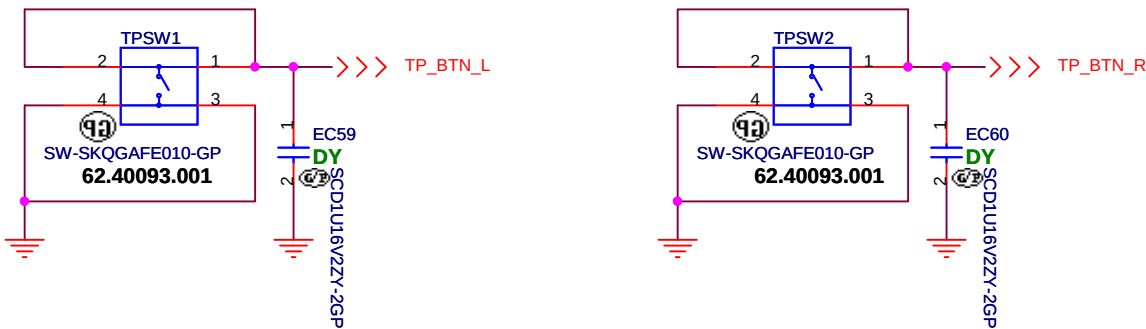
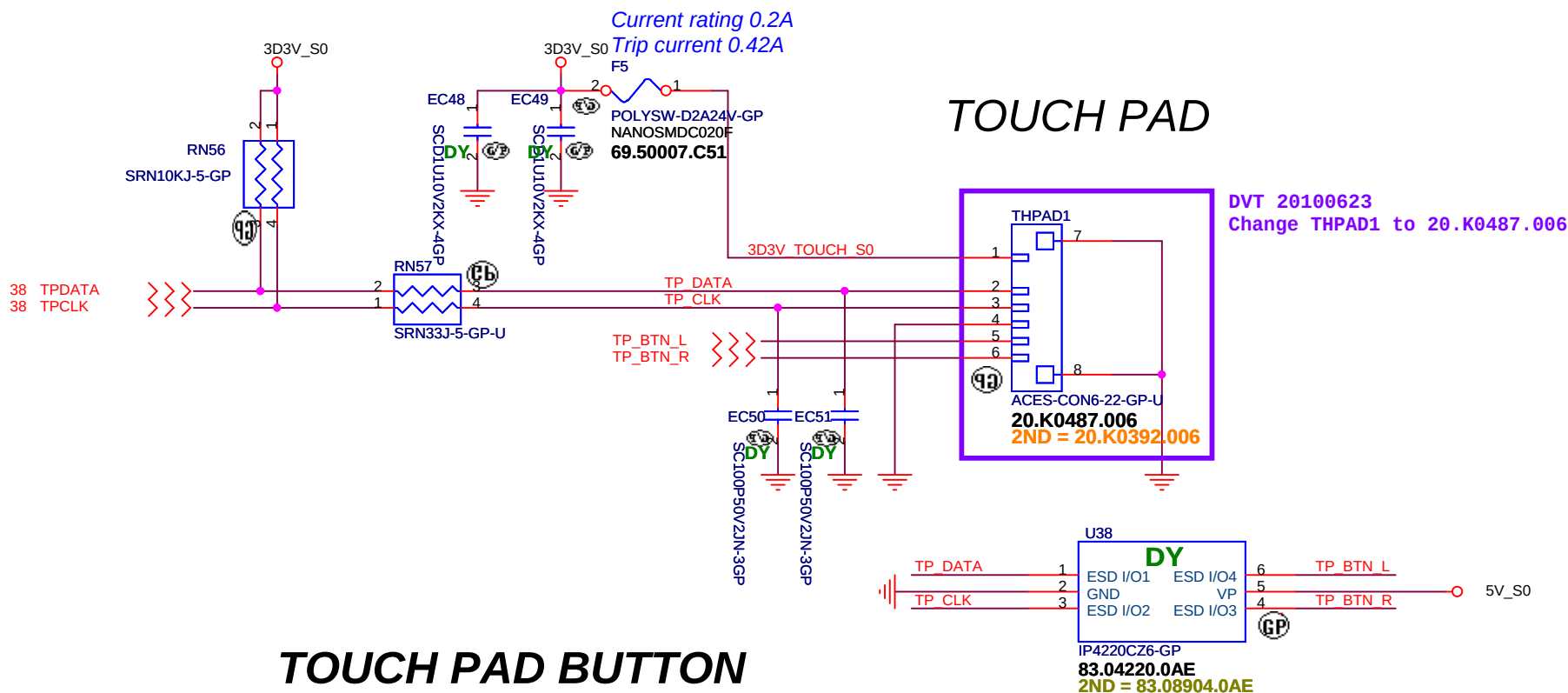


GOLDEN FINGER FOR DEBUG BOARD CONNECTOR (only install it on EVT)



BATTERY IDENTIFY



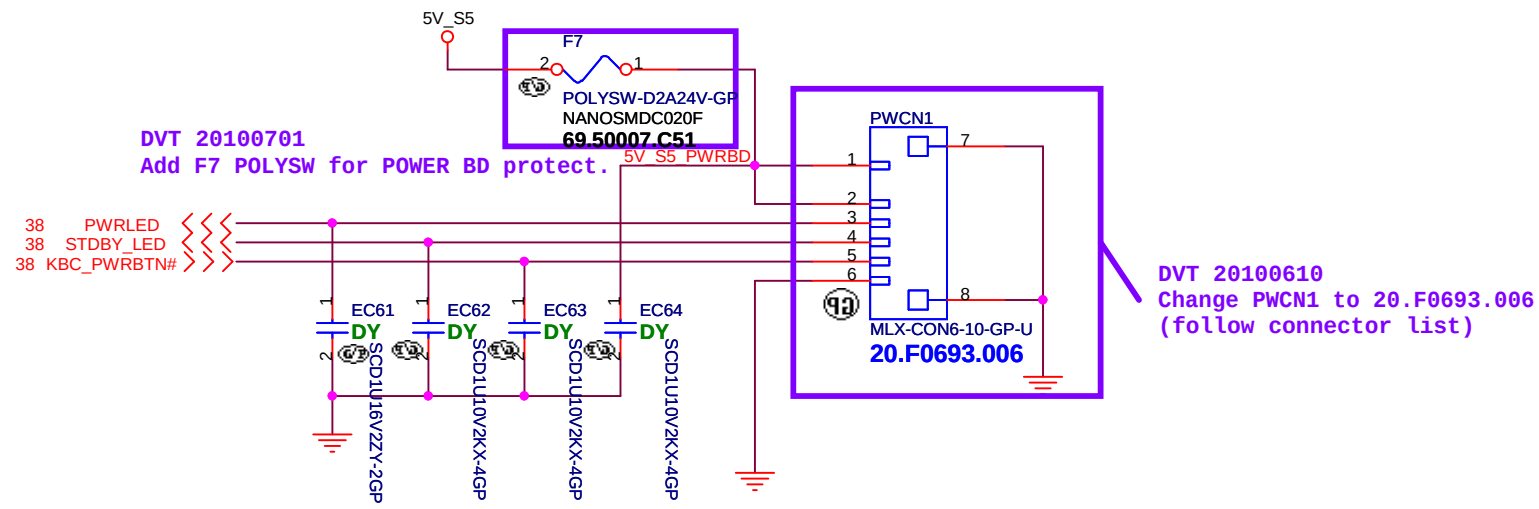


DVT 1ST

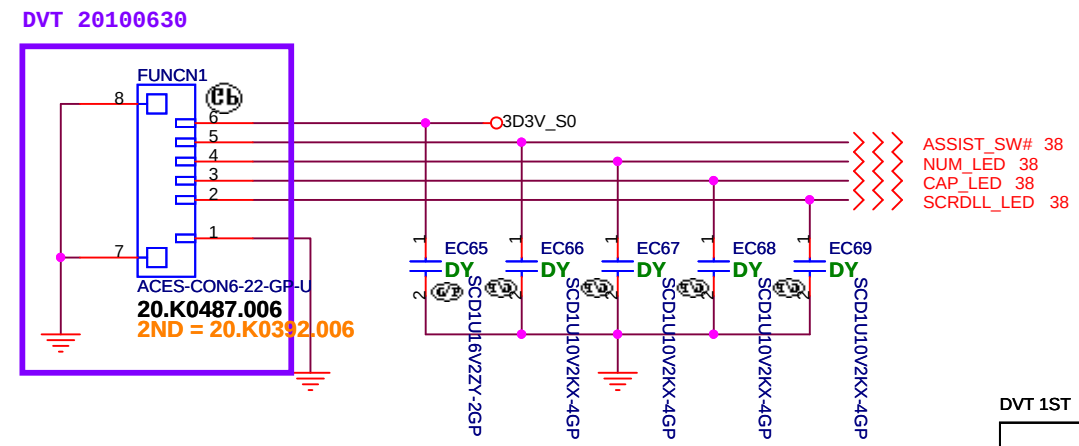
緯創資通 Wistron Corporation
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Taipei Hsien 221, Taiwan, R.O.C.

Title		
TouchPad		
Size A4	Document Number TUCANA	Rev SB
Date: Wednesday, July 07, 2010		
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POWER BUTTON BD CONN



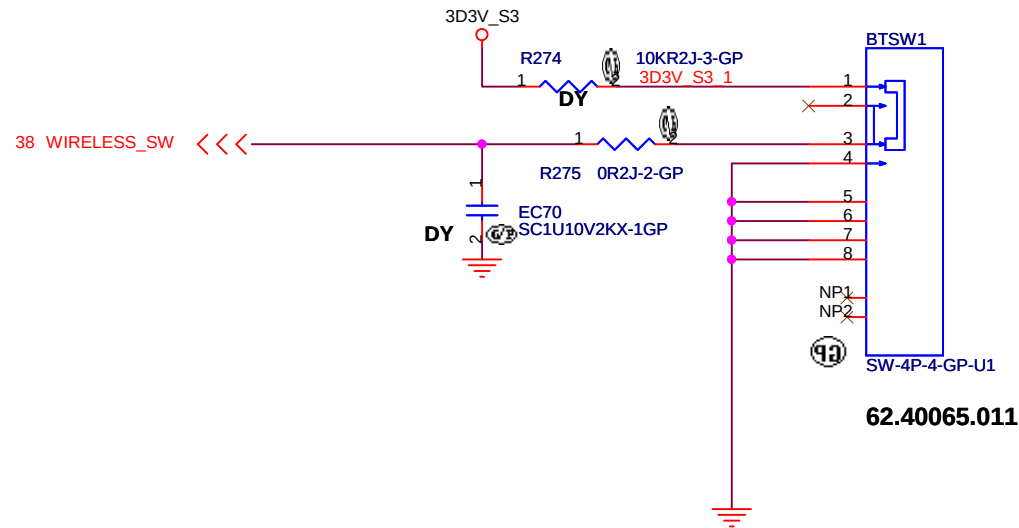
FUNCTION BD CONN



DVT 1ST

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Title	
FUNCTION BD & POWER BD	
Size	Document Number
	TUCANA
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WLAN SWITCH



DVT 1ST

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21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih,
Taipei Hsien 221, Taiwan, R.O.C.

Title

Switch

Size

Document Number

TUCANA

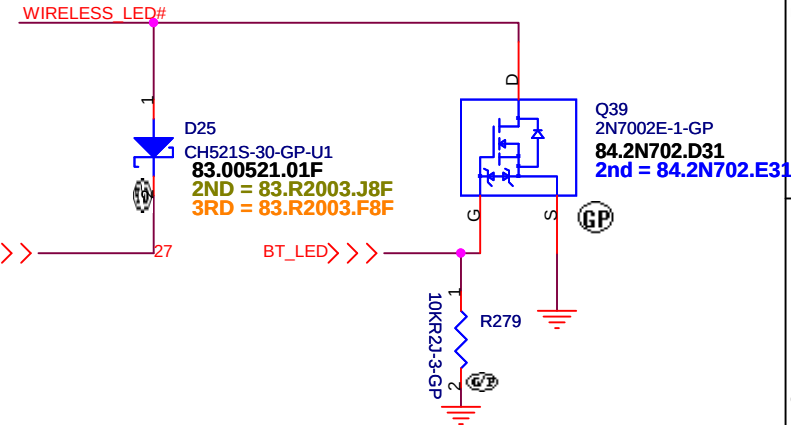
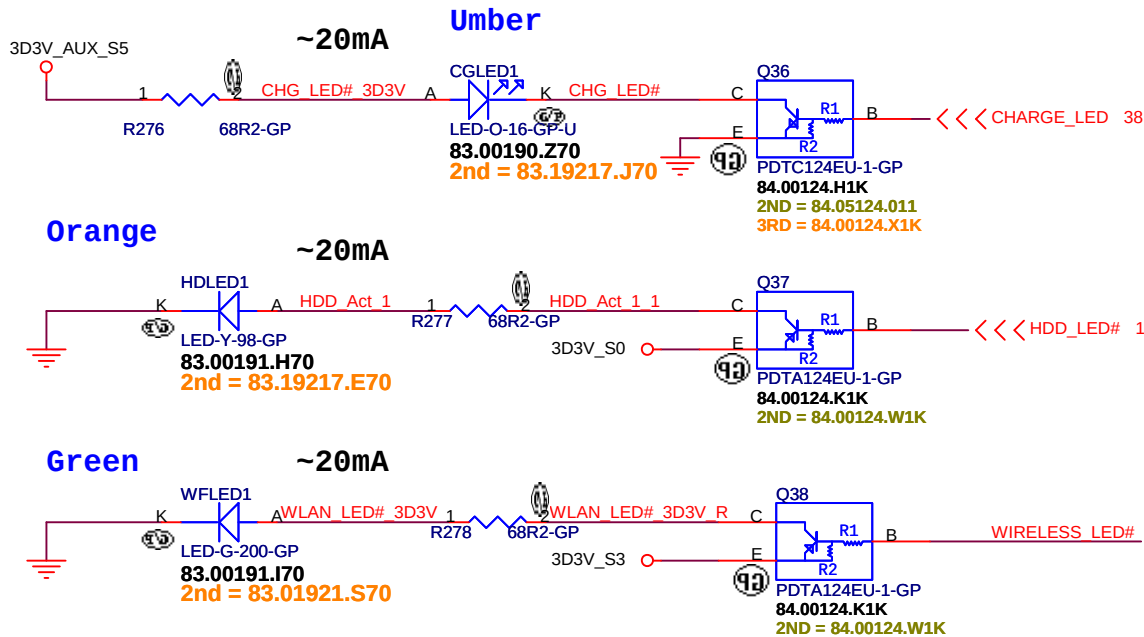
Rev

SB

Date: Wednesday, July 07, 2010

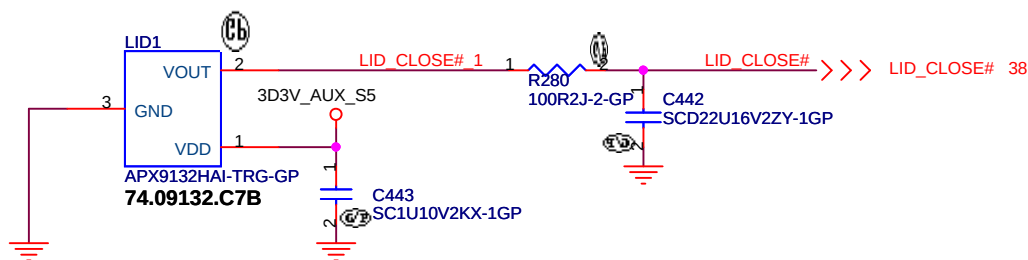
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LED



	active	High	Low
WWAN(W_DISABLE#)		ON	OFF
WLAN(WLAN_LED#)		OFF	ON
Bluetooth(BT_LED)		ON	OFF

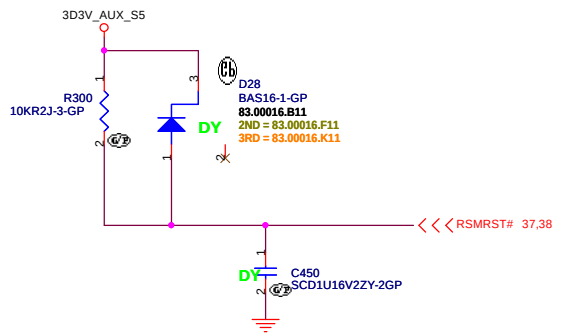
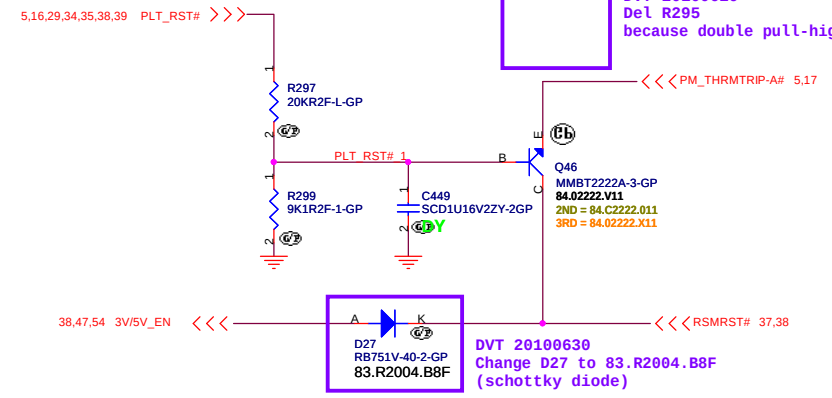
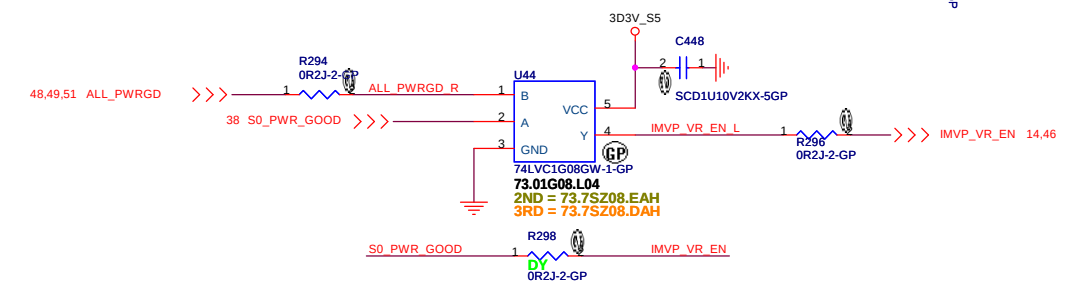
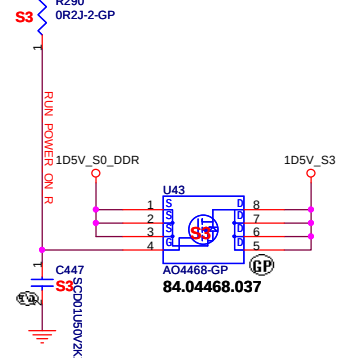
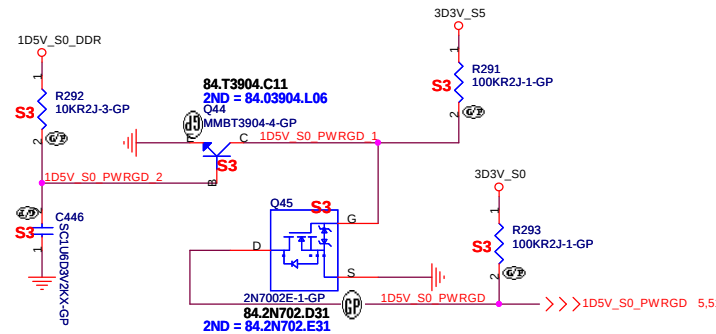
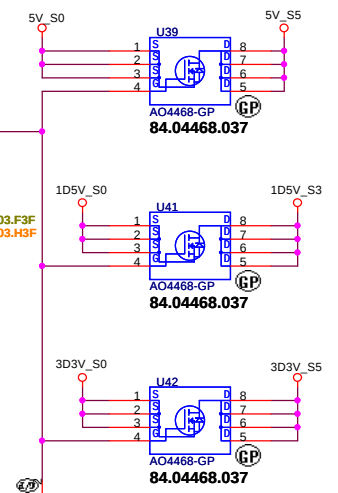
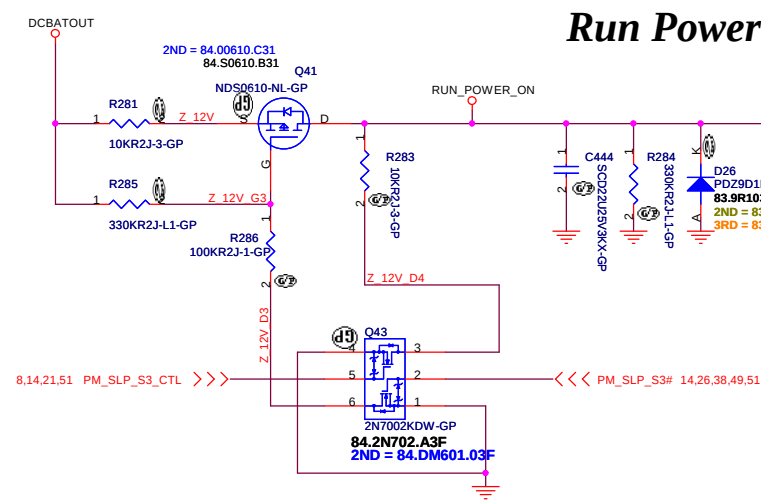
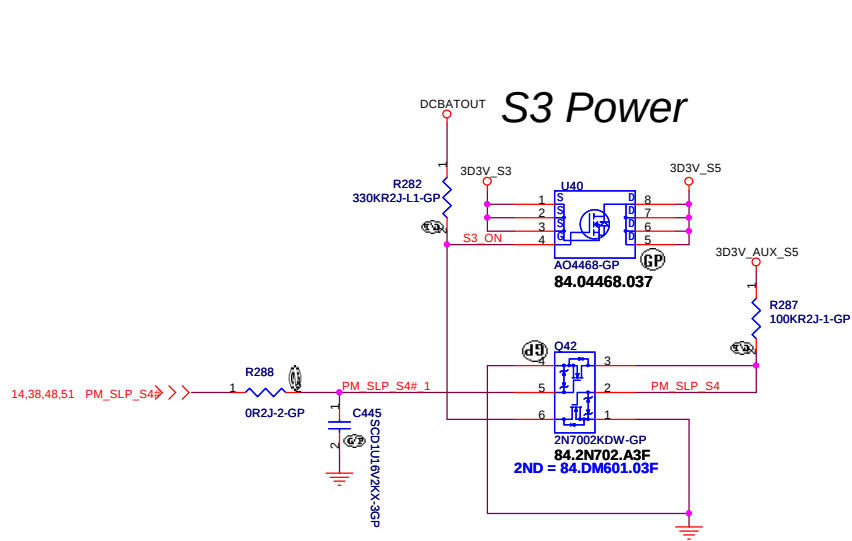
Cover Up Switch



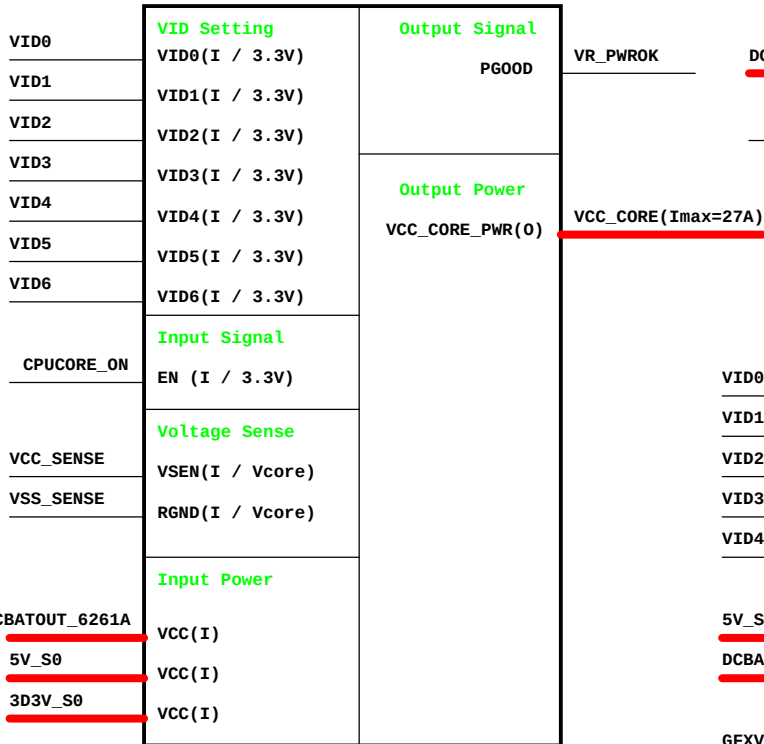
Common wireless SW(mechanical)	ON							
WLAN SW(software)	ON	OFF	ON	OFF	ON	OFF	ON	OFF
WWAN SW(software)	ON	ON	OFF	OFF	ON	ON	OFF	OFF
Bluetooth SW(software)	ON	ON	ON	ON	OFF	OFF	OFF	OFF
LED	TURN ON							OFF

DVT 1ST

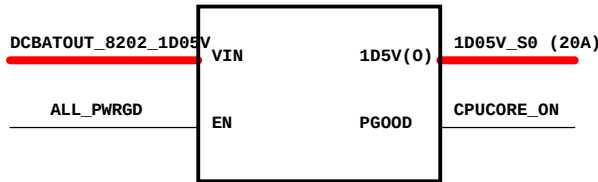
緯創資通 Wistron Corporation 21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.	
Title: Lid Switch & LED	
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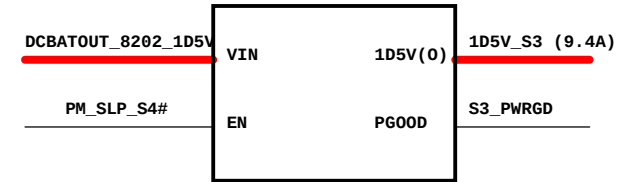
CPU_CORE
ADP3211



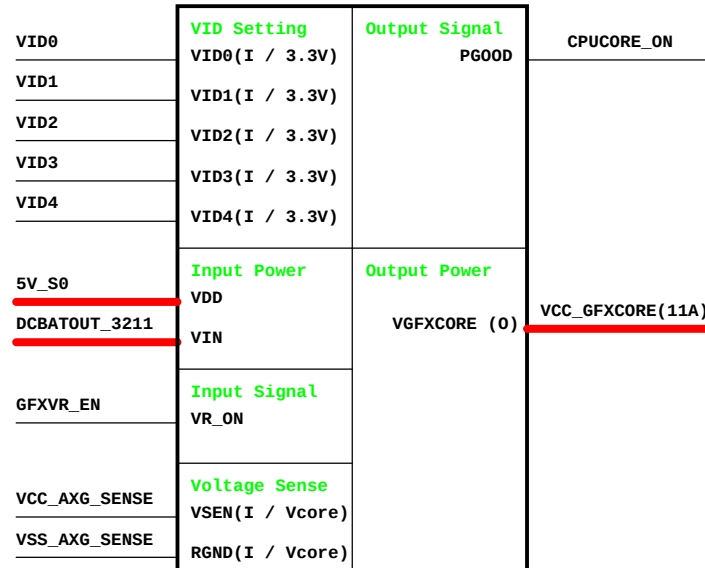
RT8209 1D05V_S0



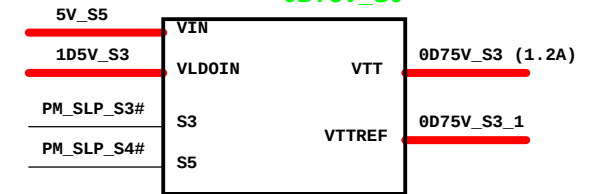
RT8209 1D5V_S3



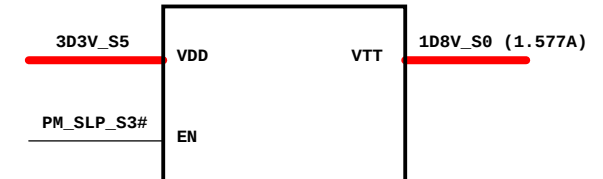
GFX_CORE/ VGA_CORE
ADP3211



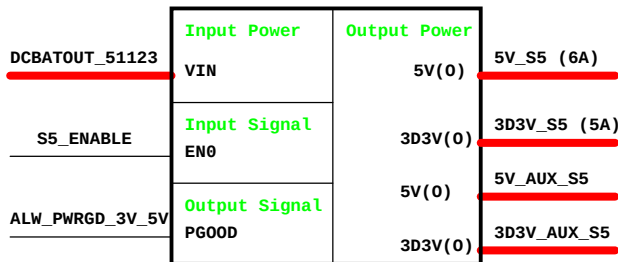
RT9026 0D75V_S0



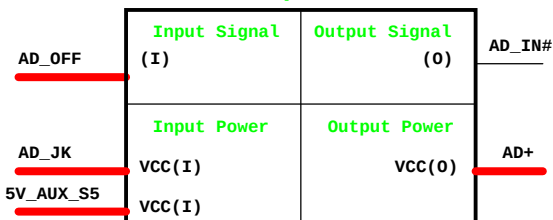
RT8015 1D8V_S0



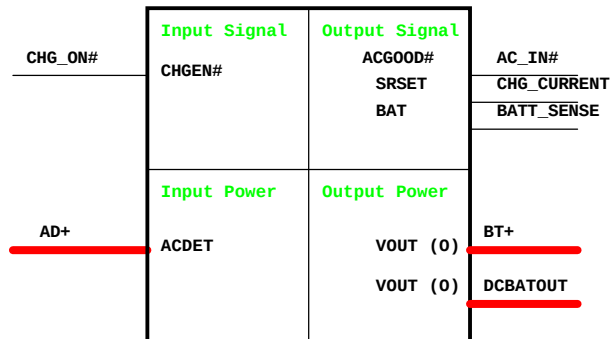
5V/3D3V
RT8223



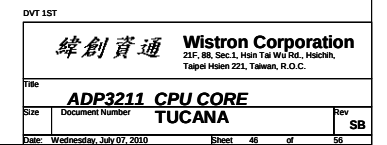
Adapter

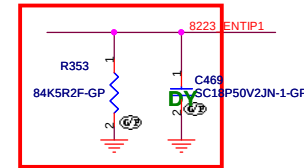
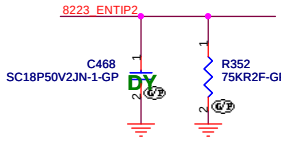
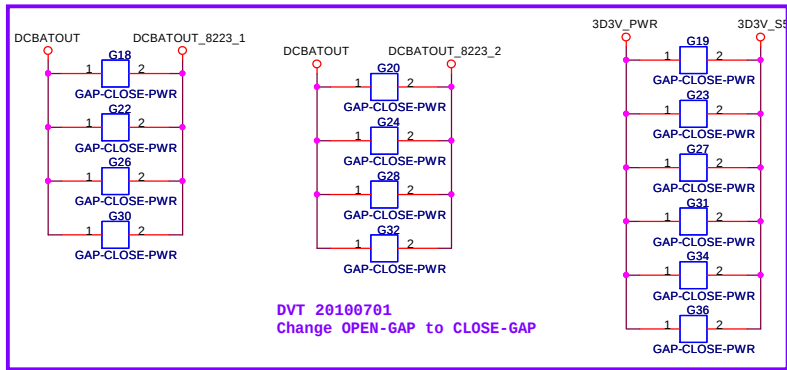


Charger BQ24751



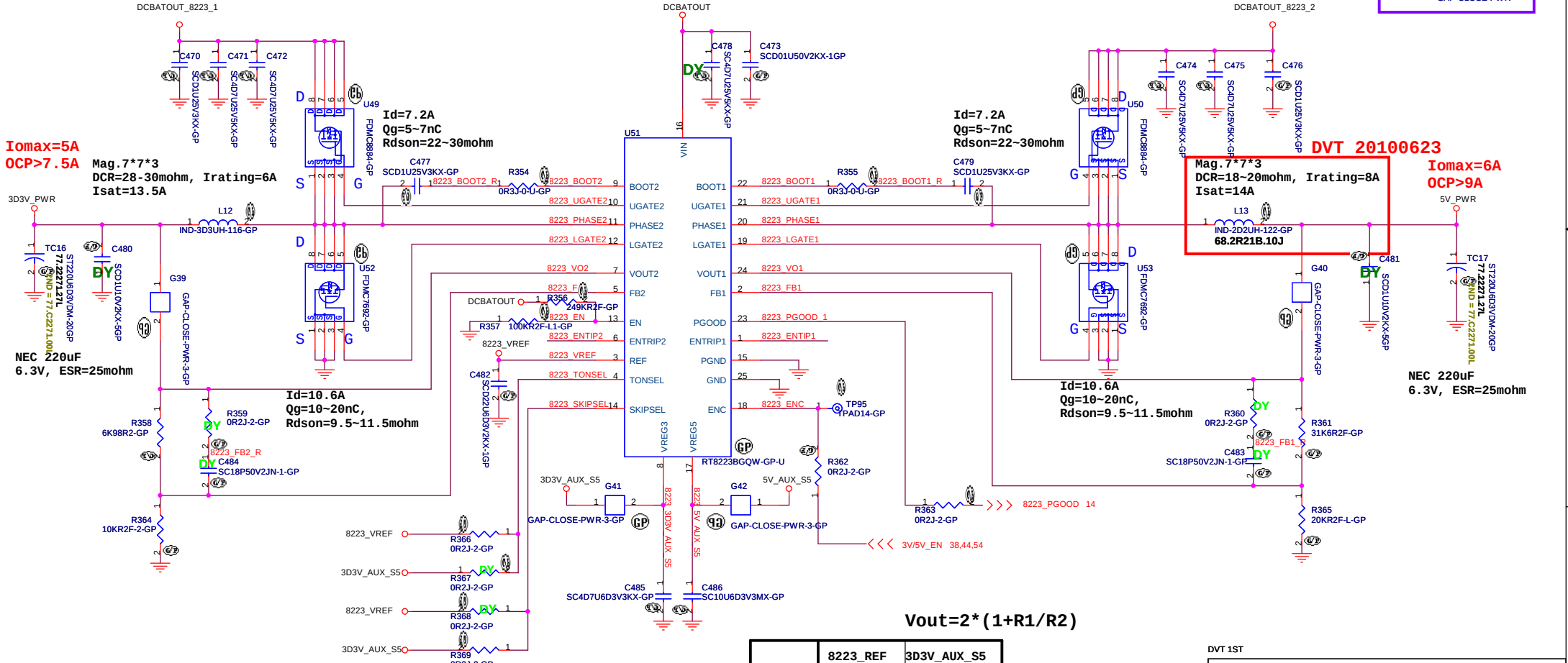
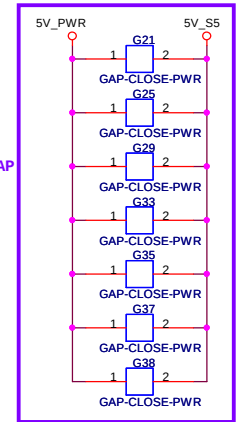
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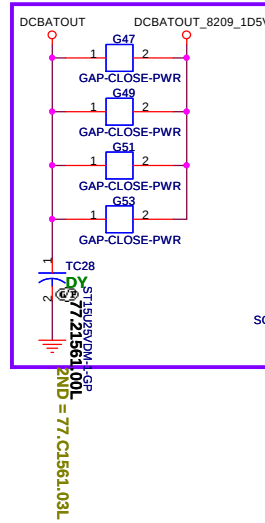
DVT 20100623

DVT 20100701
Change OPEN-GAP to CLOSE-GAP

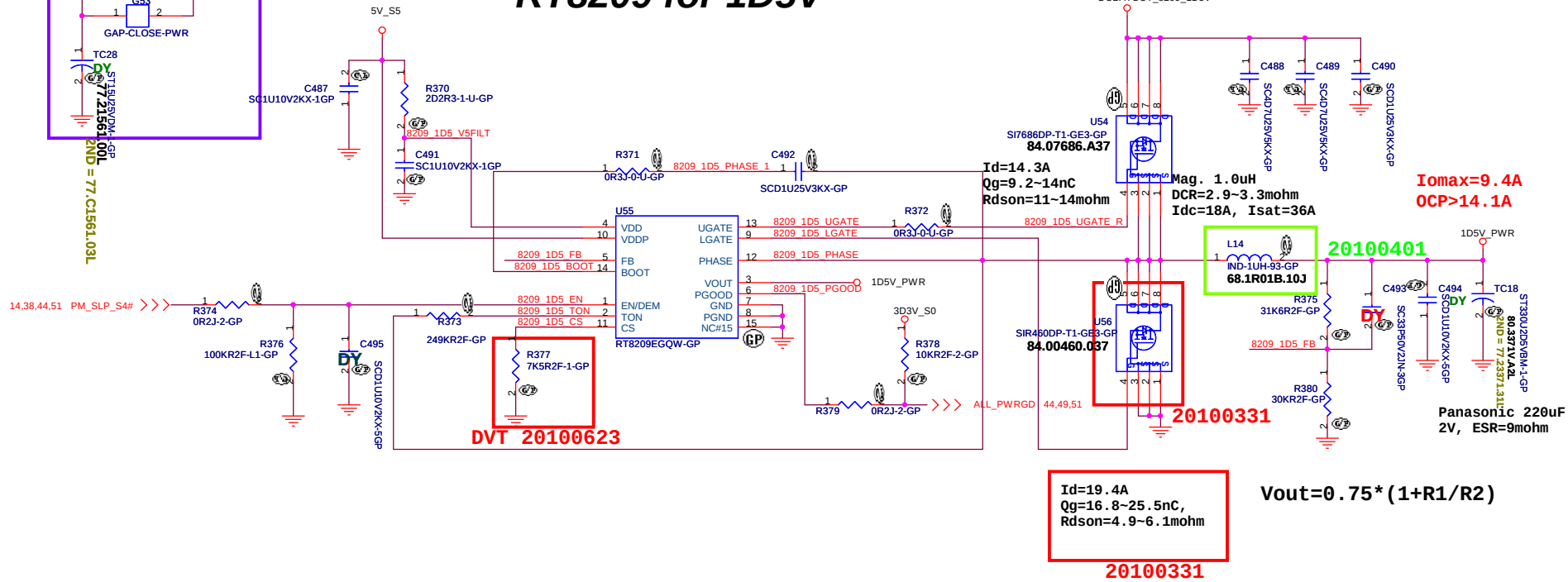


	8223_REF	3D3V_AUX_S5
SKIPSEL	PWM	00A AUTOSKIP
TONSEL	245k/CH1 305k/CH2	300k/CH1 375k/CH2

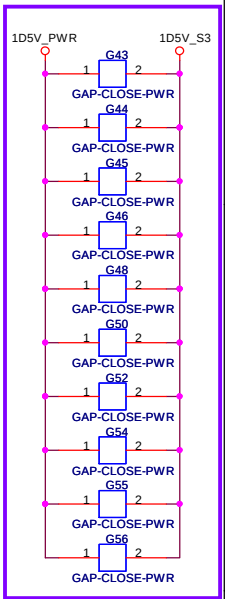
DVT 20100701
Change OPEN-GAP to
CLOSE-GAP

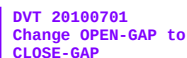


RT8209 for 1D5V

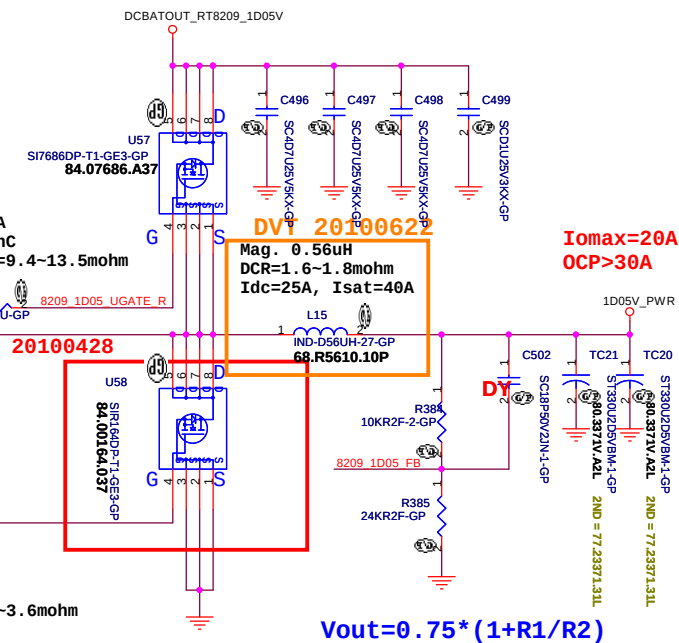
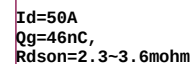


DVT 20100701
Change OPEN-GAP to
CLOSE-GAP

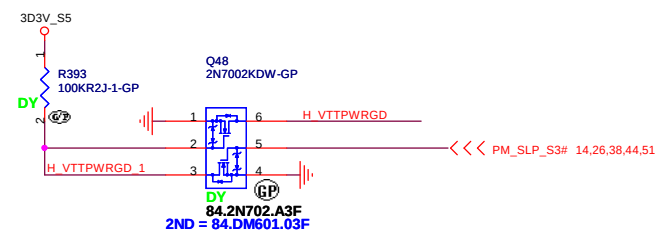




DVT 20100701
Change OPEN-GAP to
CLOSE-GAP


$$V_{out} = 0.75 * (1 + R1/R2)$$


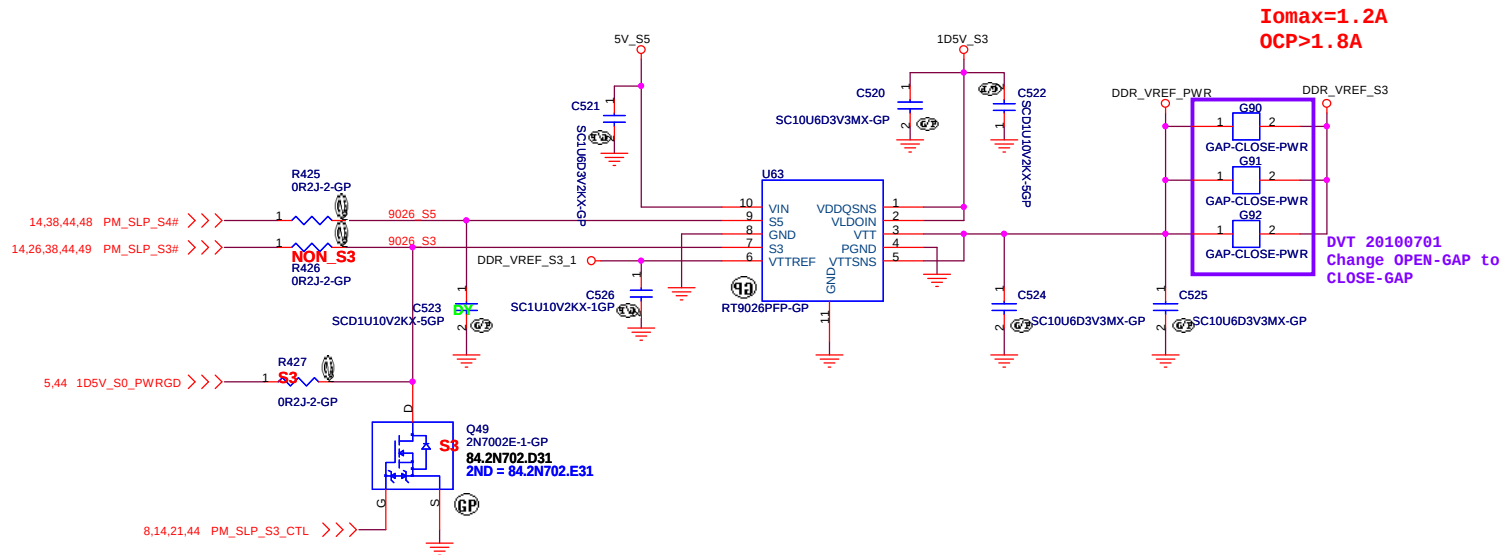
The processor needs to be warned about the VTT rails shutdown at least 100 ns before the VTT rail falls to -5% of nominal value.



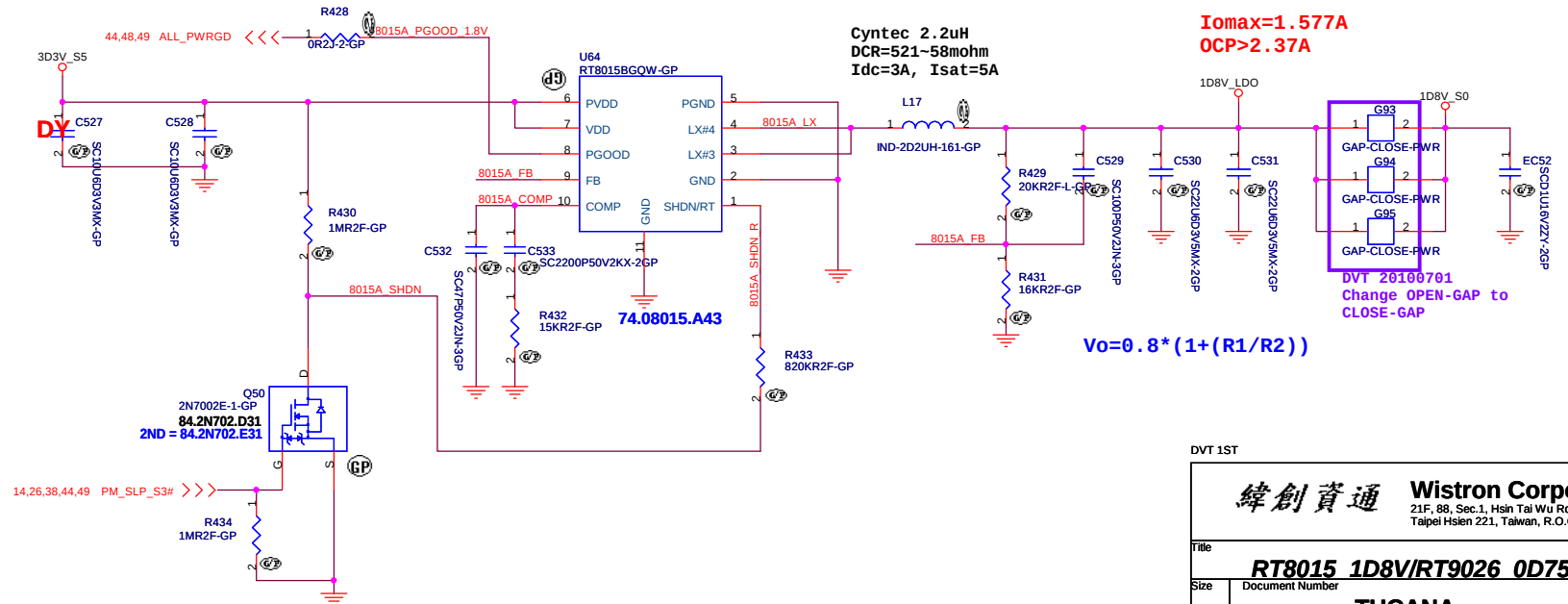
DVT 1ST



RT9026 for 0D75V_S3



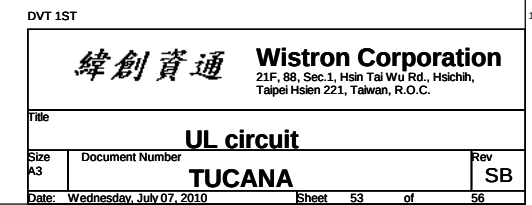
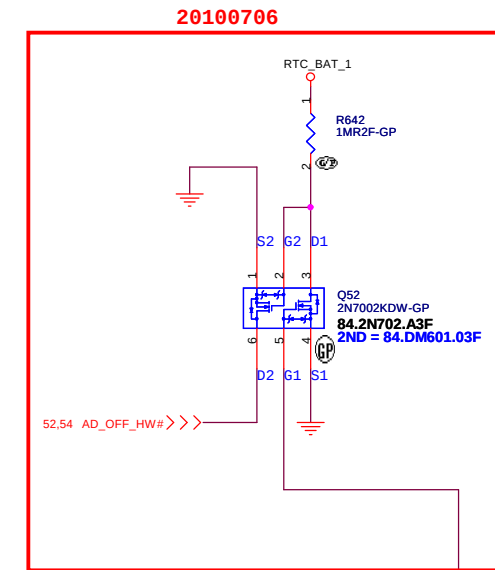
RT8015 for 1D8V_S0

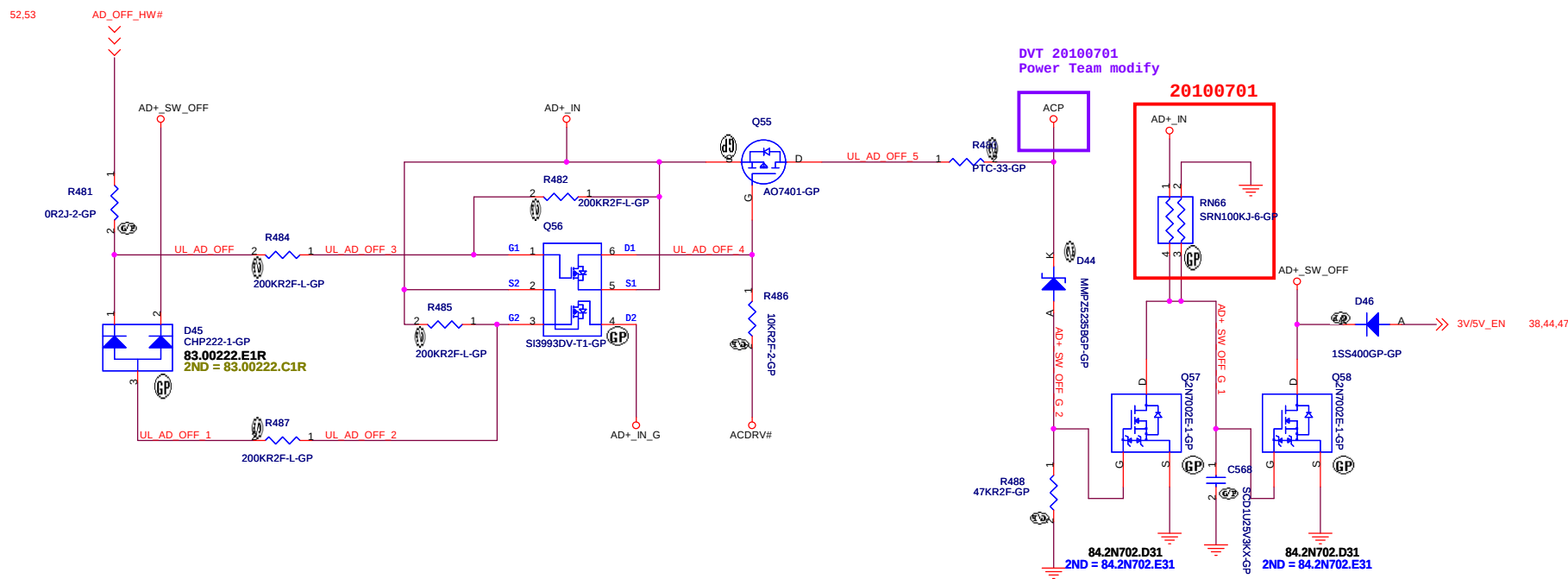


DVT 1ST

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緯創資通		Wistron Corporation 21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.	
UVP Protect			
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EVT

2010/5/17	P.52[BQ24751_Charger]	Del D31 2nd 3rd source	2010/7/2	P.38[KBC_NPCE781L / KB]	Rename H_PROCHOT# to EC_PROCHOT
2010/5/17	P.25[HDMI CONN_PS8101]	Change 2nd source to 69.4R500.151		P.5[CPU SFF(2 of 8)-CLK/Thermal]	Add R128 for EC_PROCHOT pull-low to Gnd
2010/5/24	P.26[HDD Connector]	Change R148 to 3.3K ohm ,add C437 for PM_SLP_S3# Delay		P.5[CPU SFF(2 of 8)-CLK/Thermal]	Add Q61 for EC_PROCHOT to PROCHOT#
2010/5/27	P.38[KBC_NPCE781L / KB]	Add LCD_DETECT pull-high to 3D3V_S5		P.33[Audio Jack]	Add EC176 for HP_JD# to GND , Set Dummy for ESD.
2010/5/31	P.52[BQ24751_Charger]	Mount C546,R451,R449,Q51 for battery can't Changer			Add EC177 for MIC1_JD# to GND , Set Dummy for ESD.
2010/6/1	P.24[CRT CONN]	Change F6 to 69.44002.001, for Cadiz use		P.55[EMI/Spring/Boss]	Change SPR1 to 34.42T14.002
2010/6/4	P.33[Audio Jack]	Change MICIN1 to 20.10133.L11 , follow connector list			
	P.28[USB]	Change USB1,USB2,USB3 connector to 22.10321.Q71 [follow ME connector list]	2010/7/5	P.14[PCH (3 of 9)-DMI/FDI]	Change D3 to schottky diode.
2010/6/10	P.36[AD / BATT CONN]	Change DCIN1 to 20.F0693.006 (follow connector list)		P.37[Thermal / Fan Controllor]	Delete Q29,Q30 main source 84.T3904.C11, follow CARAVEL-CP design
	P.41[FUNCTION BD & POWER BD]	Change PWCN1 to 20.F0693.006 (follow connector list)	2010/7/6	P.53[UL CIRCUIT]	Rename R642 Pin1 contact to RTC_BAT_1 (Old use RTC_BAT),follow CARAVEL-CP
2010/6/11	P.41[FUNCTION BD & POWER BD]	Del FUNCN2 connector by ME request			
	P.38[KBC_NPCE781L / KB]	Change R240 to 20K ohm SB version.			
	P.25[HDMI CONN_PS8101]	Change R614~R617 to 200R2J , Set mount. [for EMI request]			
	P.25[HDMI CONN_PS8101]	Change C283,C364 to 1uF [for EMI request]			
	P.25[HDMI CONN_PS8101]	Change C282,C285 to 1KpF [for EMI request]			
2010/6/21	P.16[PCH (5 of 9)-PCI/USB]	Add PCI_REQ2# Pull-High to 3D3V_S0 by hang-up issue			
	P.31[Audio Codec ALC269]	Change EC23,EC24 to mount [for EMI request]			
	P.55[EMI/Spring/Boss]	Change DCBATOUT capacity to mount (EC71~83,EC89,EC90,EC124,EC164~169) [for EMI request]			
		Change 5V_S0 capacity to mount (EC173~EC175) [for EMI request]			
		Change 3D3V_S0 capacity to mount (EC91~94,EC104) [for EMI request]			
		Change 3D3V_S3 capacity to mount (EC84~87) [for EMI request]			
		Change VCC_GFXCORE capacity to mount (EC142~146) [for EMI request]			
		Change VCC_CORE capacity to mount (EC136~139) [for EMI request]			
	P.36[AD / BATT CONN]	Change BT+ capacity to mount (EC32~35) [for EMI request]			
	P.23[LCD CONN]	Change C258 to 470pF (BRIGHTNESS_CN) [for EMI request]			
	P.34[CardReader RTS5186]	Add C272 between BLON_OUT_R and Gnd [for EMI request]			
		Change C576~580,C589 to 5pF [CardReader VEVs test]			
	P.24[CRT CONN]	Add 0.1uF between MS_INS# and GND [CardReader VEVs test]			
		Change R114,R115,R119,R120 to 2.7K ohm [CRT VEVs report]			
2010/6/22	P.53[UL CIRCUIT]	UL Circuit modify. [Prevent the RTC_BAT keep protecting.]			
2010/6/23	P.40[TouchPad]	Change THPAD1 to 20.K0487.006 [Follow ME connector list]			
	P.55[EMI/Spring/Boss]	Change SPR3 to DY [for EMI request]			
	P.53[UL CIRCUIT]	Add D42(83.00400.D1F), D41(83.00400.D1F) components. [Reduce the RTC_BAT discharge]			
		connect R467 pin1 to D41 and D42 pin k. [Reduce the RTC_BAT discharge]			
	P.46[ADP3211_CPU CORE]	connect D42 pin A to AD+_in. [Reduce the RTC_BAT discharge]			
		connect D41 pin A to ACP_UVP [Reduce the RTC_BAT discharge]			
		Change U45 to 84.08030.037 [Improve High side Vgs induce voltage]			
		Change U47 to 84.08028.037 [Improve High side Vgs induce voltage]			
		Change U48 to 84.08028.037 [Improve High side Vgs induce voltage]			
		add these statements. [follow Power Team design]			
	P.47[RT8223_5V/3D3V]	Change R316 to 7.87K ohm (old use 7.32K ohm) [Tune CPU Imon value]			
	P.48[RT8209_1D5V]	Change C465 to 680pF (old use 560pF) [Tune CPU load line value]			
	P.49[RT8209_1D05V]	Change R353 to 84.5K ohm (old use 97.6K ohm) [Adjust OCP value]			
		Change L13 to 2.2uH (old use 3.3uH) [IC needs higher sensing voltage to detect it.]			
	P.50[ADP3211_GFX_CORE]	Change R377 to 7.5K ohm (old use 11.5K ohm) [Adjust OCP value]			
		Change R389 to 14.3K ohm (old use 10.2K ohm) [Adjust OCP value]			
		Change L15 to 0.56uH (old use 0.45uH) [Reduce the output ripple voltage]			
		Change R419 to 56.2K ohm (old use 53.6K ohm) [Tune GFX load line value]			
		Change TC26 to mount.(old Dummy) [Improve under-shoot voltage phenomenon]			
2010/6/25	P.13[PCH (2 of 9)-PCIE/CLK/SMB]	Change C156,C157 to 12pF [for Crystal vendor Test]			
	P.29[LAN AR8131M]	Change C346 to 18pF [for Crystal vendor Test]			
	P.34[CardReader RTS5186]	Change C384,C388 to 15pF [for Crystal vendor Test]			
2010/6/29	P.17[PCH (6 of 9)-GPIO/RSVD]	Change RN31 to R648,R649 (56 ohm) for pull-high 1.05V_S0			
		Del R295 , because double pull-high			
2010/6/30	P.41[FUNCTION BD & POWER BD]	Change pin define of the FUNCN1 connector [follow the way of FFC folder for ME]			
	P.19[PCH (8 of 9)-PWR\SATA\USB]	Del R101 , only use 3D3V_S5			
	P.12[PCH (1 of 9)-SATA/RTC/HDA]	Change D1 to 83.R2003.I81 (SCHOTTKY DIODE)			
	P.25[HDMI CONN_PS8101]	Change Q12 to 84.2N702.D31 (ESD Protected 1.0KV)			
	P.44[RUN POWER]	Change D27 to 83.R2004.B8F (schottky diode)			
2010/7/1	P.46[ADP3211_CPU CORE]	Change OPEN-GAP to CLOSE-GAP (G9~14)			
	P.47[RT8223_5V/3D3V]	Change OPEN-GAP to CLOSE-GAP (G18,G22,G26,G30,G20,G24,G28,G32)			
		Change OPEN-GAP to CLOSE-GAP (G19,G23,G27,G31,G34,G36)			
	P.48[RT8209_1D5V]	Change OPEN-GAP to CLOSE-GAP (G21,G25,G29,G33,G35,G37,G38)			
		Change OPEN-GAP to CLOSE-GAP (G47,G49,G51,G53)			
	P.49[RT8209_1D05V]	Change OPEN-GAP to CLOSE-GAP (G43~46,G48,G50,G52,G54~56)			
		Change OPEN-GAP to CLOSE-GAP (G57,G58,G60,G62)			
	P.50[ADP3211_GFX_CORE]	Change OPEN-GAP to CLOSE-GAP (G59,G61,G63~80)			
	P.51[RT8015_1D8V/ RT9026_0D75]	Change OPEN-GAP to CLOSE-GAP (G81~86)			
	P.41[FUNCTION BD & POWER BD]	Change OPEN-GAP to CLOSE-GAP (G90~95)			
	P.54[UVP Protect]	Add F7 POLYSW for POWER BD 5V_S5 protect.			
		Delete R483 and add RN66. (RN66 part number is 66.10436.04L)			
		Connect AD+_IN to RN66 pin 1.			
		Connect RN66 pin2 to GND.			
	P.53[UL CIRCUIT]	Connect RN66 pin3 and pin4 to AD+_SW_OFF_G_1			
		Change R468 part number to the 64.36025.6DL			
		Change R469 to the part number 64.30025.6DL			
		Cummy R471 and mount D39.			
		Delete D40 and RN58.			
		Add R642. (Part number is 64.10045.6DL)			
		Connect R642 pin 1 to RTC_BAT.			
		Connect R642 pin2 to Q52 pin 2 and pin3.			
		Connect ACP to R435 pin 1.			
	P.52[BQ24751_Charger]	UPDATE BTCN1 PCB LAYOUT (REMOVE THE NPTH)			
	P.27[Bluetooth]				

<Core Design>